

8-Bit

SAL-XC866

8-Bit Single-Chip Microcontroller

Data Sheet V1.1 2012-12

Microcontrollers

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SAL-XC866

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Data Sheet V1.1 2012-12

Microcontrollers



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8-Bit Single-Chip Microcontroller XC800 Family

SAL-XC866

1 Summary of Features

- High-performance XC800 Core
 - compatible with standard 8051 processor
 - two clocks per machine cycle architecture (for memory access without wait state)
 - two data pointers
- On-chip memory
 - 8 Kbytes of Boot ROM
 - 256 bytes of RAM
 - 512 bytes of XRAM
 - 4/8/16 Kbytes of Flash

(includes memory protection strategy)

I/O port supply at 3.3 V/5.0 V and core logic supply at 2.5 V (generated by embedded voltage regulator)

(further features are on next page)

| 4K/ 8K/16K | K/ 8K/16K Bytes Flash On-Chip Debug Support | | UART | SSC | Port 0 | 6-bit Digital VO | |
|----------------------|---|-------------------|-------------------|--------------------------|----------------------------|------------------|------------------|
| Boot ROM 8K Bytes | | | | Capture/Co 16 | ompare Unit -bit | Port 1 | 5-bit Digital VO |
| XRAM 512 Bytes | XC800 Core | | | — — — — — Compa 16 | are Unit -bit | Port 2 | - |
| RAM 256 Bytes | Timer 0 16-bit | Timer 1 16-bit | Timer 2 16-bit | Watchdog Timer | ADC 10-bit 8-channel | Port 3 | 8-bit Digital VO |
| · | | | | | | | - |

Figure 1 SAL-XC866 Functional Units



Summary of Features

Features (continued):

- Reset generation
 - Power-On reset
 - Hardware reset
 - Brownout reset for core logic supply
 - Watchdog timer reset
 - Power-Down Wake-up reset
- On-chip OSC and PLL for clock generation
 - PLL loss-of-lock detection
- Power saving modes
 - slow-down mode
 - idle mode
 - power-down mode with wake-up capability via RXD or EXINT0
 - clock gating control to each peripheral
- Programmable 16-bit Watchdog Timer (WDT)
- Four ports
 - 19 pins as digital I/O
 - 8 pins as digital/analog input
- 8-channel, 10-bit ADC
- Three 16-bit timers
 - Timer 0 and Timer 1 (T0 and T1)
 - Timer 2
- Capture/compare unit for PWM signal generation (CCU6)
- Full-duplex serial interface (UART)
- Synchronous serial channel (SSC)
- On-chip debug support
 - 1 Kbyte of monitor ROM (part of the 8-Kbyte Boot ROM)
- 64 bytes of monitor RAM
- PG-TSSOP-38 pin package
- Temperature range T_A:
 - SAL (-40 to 150 °C)



Summary of Features

SAL-XC866 Variant Devices

The SAL-XC866 product family features devices with different configurations and program memory sizes, offering cost-effective solution for different application requirements.

The list of SAL-XC866 devices and their differences are summarized in Table 1.

| Device Type | Device Name | Power Supply (V) | P-Flash Size (Kbytes) | D-Flash Size (Kbytes) | LIN BSL Support |
|---------------------|-----------------|---------------------|-----------------------------|-----------------------------|--------------------|
| Flash ¹⁾ | SAL-XC866L-4FRA | 5.0 | 12 | 4 | Yes |
| | SAL-XC866L-2FRA | 5.0 | 4 | 4 | Yes |
| | SAL-XC866L-4FRA | 3.3 | 12 | 4 | Yes |
| | SAL-XC866L-2FRA | 3.3 | 4 | 4 | Yes |

Table 1 Device Summary

¹⁾ The flash memory (P-Flash and D-Flash) can be used for code or data.

Ordering Information

The ordering code for Infineon Technologies microcontrollers provides an exact reference to the required product. This ordering code identifies:

- The derivative itself, i.e. its function set, the temperature range, and the supply voltage
- the package and the type of delivery

For the available ordering codes for the SAL-XC866, please refer to your responsible sales representative or your local distributor.

As this document refers to all the derivatives, some descriptions may not apply to a specific product. For simplicity all versions are referred to by the term SAL-XC866 throughout this document.



2 General Device Information

2.1 Block Diagram



Figure 2 SAL-XC866 Block Diagram



2.2 Logic Symbol



Figure 3 SAL-XC866 Logic Symbol



2.3 Pin Configuration



Figure 4 SAL-XC866 Pin Configuration, PG-TSSOP-38 Package (top view)



2.4 Pin Definitions and Functions

| Table 2 | Pin D | efinitio | finitions and Functions | | | |
|---------|---------------|----------|-------------------------|--|--|--|
| Symbol | Pin Number | Туре | Reset State | Function | | |
| P0 | | I/O | | Port 0 Port 0 is a 6- port. It can b JTAG, CCU6 | bit bidirectional general purpose I/O e used as alternate functions for the 5, UART, and the SSC. | |
| P0.0 | 12 | | Hi-Z | TCK_0 T12HR_1 | JTAG Clock Input CCU6 Timer 12 Hardware Run Input | |
| | | | | CLKOUT RXDO_1 | channel 1 Clock Output UART Transmit Data Output | |
| P0.1 | 14 | | Hi-Z | TDI_0 T13HR_1 | JTAG Serial Data Input CCU6 Timer 13 Hardware Run | |
| | | | | RXD_1 COUT61_1 | UART Receive Data Input Output of Capture/Compare channel 1 | |
| P0.2 | 13 | | PU | EXF2_1 CTRAP_2 TDO_0 TXD_1 | CCU6 Trap Input JTAG Serial Data Output UART Transmit Data Output/ Clock Output | |
| P0.3 | 2 | | Hi-Z | SCK_1 COUT63_1 | SSC Clock Input/Output Output of Capture/Compare channel 3 | |
| P0.4 | 3 | | Hi-Z | MTSR_1 CC62_1 | SSC Master Transmit Output/ Slave Receive Input Input/Output of Capture/Compare channel 2 | |
| P0.5 | 4 | | Hi-Z | MRST_1 EXINT0_0 COUT62_1 | SSC Master Receive Input/ Slave Transmit Output External Interrupt Input 0 Output of Capture/Compare channel 2 | |



| Table 2 | Pin Definitions and Functions (cont'd) | | | | |
|---------|--|------|----------------|---|--|
| Symbol | Pin Number | Туре | Reset State | Function | |
| P1 | | I/O | | Port 1 Port 1 is a 5- port. It can b JTAG, CCU6 | bit bidirectional general purpose I/O e used as alternate functions for the 5, UART, and the SSC. |
| P1.0 | 27 | | PU | RXD_0 T2EX | UART Receive Data Input Timer 2 External Trigger Input |
| P1.1 | 28 | | PU | EXINT3 TDO_1 TXD_0 | External Interrupt Input 3 JTAG Serial Data Output UART Transmit Data Output/ Clock Output |
| P1.5 | 29 | | PU | CCPOS0_1 EXINT5 EXF2_0 RXDO_0 | CCU6 Hall Input 0 External Interrupt Input 5 TImer 2 External Flag Output UART Transmit Data Output |
| P1.6 | 9 | | PU | CCPOS1_1 T12HR_0 EXINT6 | CCU6 Hall Input 1 CCU6 Timer 12 Hardware Run Input External Interrupt Input 6 |
| P1.7 | 10 | | PU | CCPOS2_1 T13HR_0 | CCU6 Hall Input 2 CCU6 Timer 13 Hardware Run Input |
| | | | | P1.5 and P1 select output | .6 can be used as a software chip t for the SSC. |



| Symbol | Pin Number | Туре | Reset State | Function | |
|--------|---------------|------|----------------|---|--|
| P2 | | I | | Port 2 Port 2 is an 8 can be used inputs of the analog inputs | bit general purpose input-only port. It as alternate functions for the digital JTAG and CCU6. It is also used as the s for the ADC. |
| P2.0 | 15 | | Hi-Z | CCPOS0_0 EXINT1 T12HR_2 | CCU6 Hall Input 0 External Interrupt Input 1 CCU6 Timer 12 Hardware Run Input |
| | | | | TCK_1 CC61_3 AN0 | JTAG Clock Input Input of Capture/Compare channel 1 Analog Input 0 |
| P2.1 | 16 | | Hi-Z | CCPOS1_0 EXINT2 T13HR_2 | CCU6 Hall Input 1 External Interrupt Input 2 CCU6 Timer 13 Hardware Run |
| | | | | TDI_1 CC62_3 AN1 | JTAG Serial Data Input Input of Capture/Compare channel 2 Analog Input 1 |
| P2.2 | 17 | | Hi-Z | CCPOS2_0 CTRAP_1 CC60_3 AN2 | CCU6 Hall Input 2 CCU6 Trap Input Input of Capture/Compare channel 0 Analog Input 2 |
| P2.3 | 20 | | Hi-Z | AN3 | Analog Input 3 |
| P2.4 | 21 | | Hi-Z | AN4 | Analog Input 4 |
| P2.5 | 22 | | Hi-Z | AN5 | Analog Input 5 |
| P2.6 | 23 | | Hi-Z | AN6 | Analog Input 6 |
| P2.7 | 26 | | Hi-Z | AN7 | Analog Input 7 |



| Symbol | Pin Number | Туре | Reset State | Function | |
|--------|---------------|------|----------------|--------------------------------|---|
| P3 | | 1 | | Port 3 | |
| | | | | Port 3 is a bio can be used | directional general purpose I/O port. It as alternate functions for the CCU6. |
| P3.0 | 32 | | Hi-Z | CCPOS1_2 CC60_0 | CCU6 Hall Input 1 Input/Output of Capture/Compare channel 0 |
| P3.1 | 33 | | Hi-Z | CCPOS0_2 CC61_2 | CCU6 Hall Input 0 Input/Output of Capture/Compare channel 1 |
| | | | | COUT60_0 | Output of Capture/Compare channel 0 |
| P3.2 | 34 | | Hi-Z | CCPOS2_2 CC61_0 | CCU6 Hall Input 2 Input/Output of Capture/Compare channel 1 |
| P3.3 | 35 | | Hi-Z | COUT61_0 | Output of Capture/Compare channel 1 |
| P3.4 | 36 | | Hi-Z | CC62_0 | Input/Output of Capture/Compare channel 2 |
| P3.5 | 37 | | Hi-Z | COUT62_0 | Output of Capture/Compare channel 2 |
| P3.6 | 30 | | PD | CTRAP_0 | CCU6 Trap Input |
| P3.7 | 31 | | Hi-Z | EXINT4 COUT63_0 | External Interrupt Input 4 Output of Capture/Compare channel 3 |

Table 2 Pin Definitions and Functions (cont'd)



| Table 2 | Pin Definitions and Functions (cont'd) | | | | | | |
|-------------------|--|------|----------------|---|--|--|--|
| Symbol | Pin Number | Туре | Reset State | Function | | | |
| V _{DDP} | 18 | - | - | I/O Port Supply (3.3 V/5.0 V) Also used by EVR and analog modules. | | | |
| V _{SSP} | 19 | _ | - | I/O Port Ground | | | |
| V _{DDC} | 8 | - | - | Core Supply Monitor (2.5 V) | | | |
| V _{SSC} | 7 | _ | - | Core Supply Ground | | | |
| V _{AREF} | 25 | - | - | ADC Reference Voltage | | | |
| V _{AGND} | 24 | - | - | ADC Reference Ground | | | |
| XTAL1 | 6 | I | Hi-Z | External Oscillator Input (NC if not needed) | | | |
| XTAL2 | 5 | 0 | Hi-Z | External Oscillator Output (NC if not needed) | | | |
| TMS | 11 | I | PD | Test Mode Select | | | |
| RESET | 38 | I | PU | Reset Input | | | |
| MBC ¹⁾ | 1 | I | PU | Monitor & BootStrap Loader Control | | | |

¹⁾ An external pull-up device in the range of 4.7 k Ω to 100 k Ω is required to enter user mode. Alternatively MBC can be tied to high if alternate functions (for debugging) of the pin are not utilized.



3 Functional Description

3.1 Processor Architecture

The SAL-XC866 is based on a high-performance 8-bit Central Processing Unit (CPU) that is compatible with the standard 8051 processor. While the standard 8051 processor is designed around a 12-clock machine cycle, the SAL-XC866 CPU uses a 2-clock machine cycle. This allows fast access to ROM or RAM memories without wait state. Access to the Flash memory, however, requires an additional wait state (one machine cycle). The instruction set consists of 45% one-byte, 41% two-byte and 14% three-byte instructions.

The SAL-XC866 CPU provides a range of debugging features, including basic stop/start, single-step execution, breakpoint support and read/write access to the data memory, program memory and SFRs. **Figure 5** shows the CPU functional blocks.



Figure 5 CPU Block Diagram



3.2 Memory Organization

The SAL-XC866 CPU operates in the following five address spaces:

- 8 Kbytes of Boot ROM program memory
- 256 bytes of internal RAM data memory
- 512 bytes of XRAM memory
- a 128-byte Special Function Register area
- 4/8/16 Kbytes of Flash program memory





Figure 6 illustrates the memory address spaces of the SAL-XC866-4FR devices.





3.2.1 Memory Protection Strategy

The SAL-XC866 memory protection strategy includes:

- Read-out protection: The Flash Memory can be enabled for read-out protection and ROM memory is always protected.
- Program and erase protection: The Flash memory in all devices can be enabled for program and erase protection.

Flash memory protection is available in two modes:

- Mode 0: Only the P-Flash is protected; the D-Flash is unprotected
- Mode 1: Both the P-Flash and D-Flash are protected

The selection of each protection mode and the restrictions imposed are summarized in **Table 3**.

| Mode | 0 | 1 |
|---------------------------------|--|--|
| Activation | Program a valid password via BSL m | ode 6 |
| Selection | MSB of password = 0 | MSB of password = 1 |
| P-Flash contents can be read by | Read instructions in the P-Flash | Read instructions in the P-Flash or D-Flash |
| P-Flash program and erase | Not possible | Not possible |
| D-Flash contents can be read by | Read instructions in any program memory | Read instructions in the P-Flash or D-Flash |
| D-Flash program | Possible | Not possible |
| D-Flash erase | Possible, on the condition that bit DFLASHEN in register MISC_CON is set to 1 prior to each erase operation | Not possible |

Table 3 Flash Protection Modes

BSL mode 6, which is used for enabling Flash protection, can also be used for disabling Flash protection. Here, the programmed password must be provided by the user. A password match triggers an automatic erase of the read-protected Flash contents, see **Table 4**, and the programmed password is erased. The Flash protection is then disabled upon the next reset.

For XC866-2FR and XC866-4FR devices:

The selection of protection type is summarized in Table 4.



Table 4 Flash Protection Type for XC866-2FR and XC866-4FR devices

| PASSWORD | Type of Protection | Flash Banks to Erase when Unprotected |
|-----------------------|-------------------------|--|
| 1XXXXXXX _B | Flash Protection Mode 1 | All Banks |
| OXXXXXXAB | Flash Protection Mode 0 | P-Flash Bank |

Although no protection scheme can be considered infallible, the SAL-XC866 memory protection strategy provides a very high level of protection for a general purpose microcontroller.



3.2.2 Special Function Register

The Special Function Registers (SFRs) occupy direct internal data memory space in the range 80_{H} to FF_H. All registers, except the program counter, reside in the SFR area. The SFRs include pointers and registers that provide an interface between the CPU and the on-chip peripherals. As the 128-SFR range is less than the total number of registers required, address extension mechanisms are required to increase the number of addressable SFRs. The address extension mechanisms include:

- Mapping
- Paging

01/00010

3.2.2.1 Address Extension by Mapping

Address extension is performed at the system level by mapping. The SFR area is extended into two portions: the standard (non-mapped) SFR area and the mapped SFR area. Each portion supports the same address range 80_H to FF_H, bringing the number of addressable SFRs to 256. The extended address range is not directly controlled by the CPU instruction itself, but is derived from bit RMAP in the system control register SYSCON0 at address $8F_H$. To access SFRs in the mapped area, bit RMAP in SFR SYSCON0 must be set. Alternatively, the SFRs in the standard area can be accessed by clearing bit RMAP. The SFR area can be selected as shown in Figure 7.

| System Co | , ontrol Reg | jister 0 | | | | Rese | t Value: 00 _H |
|-----------|-----------------|----------|-----|---|----|------|--------------------------|
| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
| | I | 0 | 1 1 | | 1 | 0 | RMAP |
| L | 1 | r | 11 | | rw | r | rw |

| Field | Bits | Туре | Description |
|-------|---------|------|---|
| RMAP | 0 | rw | Special Function Register Map Control The access to the standard SFR area is enabled. The access to the mapped SFR area is enabled. |
| 1 | 2 | rw | Reserved Returns the last value if read; should be written with 1. |
| 0 | 1,[7:3] | r | Reserved Returns 0 if read; should be written with 0. |

Note: The RMAP bit must be cleared/set by ANL or ORL instructions. The rest bits of SYSCON0 should not be modified.

As long as bit RMAP is set, the mapped SFR area can be accessed. This bit is not cleared automatically by hardware. Thus, before standard/mapped registers are accessed, bit RMAP must be cleared/set, respectively, by software.



Figure 7 Address Extension by Mapping



3.2.2.2 Address Extension by Paging

Address extension is further performed at the module level by paging. With the address extension by mapping, the SAL-XC866 has a 256-SFR address range. However, this is still less than the total number of SFRs needed by the on-chip peripherals. To meet this requirement, some peripherals have a built-in local address extension mechanism for increasing the number of addressable SFRs. The extended address range is not directly controlled by the CPU instruction itself, but is derived from bit field PAGE in the module page register MOD_PAGE. Hence, the bit field PAGE must be programmed before accessing the SFR of the target module. Each module may contain a different number of pages and a different number of SFRs per page, depending on the specific requirement. Besides setting the correct RMAP bit value to select the SFR area, the user must also ensure that a valid PAGE is selected to target the desired SFR. A page inside the extended address range can be selected as shown in Figure 8.



Figure 8 Address Extension by Paging

In order to access a register located in a page different from the actual one, the current page must be left. This is done by reprogramming the bit field PAGE in the page register. Only then can the desired access be performed.

If an interrupt routine is initiated between the page register access and the module register access, and the interrupt needs to access a register located in another page, the current page setting can be saved, the new one programmed and finally, the old page setting restored. This is possible with the storage fields MOD_STx (x = 0 - 3) for the save and restore action of the current page setting. By indicating which storage bit field should be used in parallel with the new page value, a single write operation can:

- Save the contents of PAGE in MOD_STx before overwriting with the new value (this is done in the beginning of the interrupt routine to save the current page setting and program the new page number); or
- Overwrite the contents of PAGE with the contents of MOD_STx, ignoring the value written to the bit positions of PAGE

(this is done at the end of the interrupt routine to restore the previous page setting before the interrupt occurred)



Figure 9 Storage Elements for Paging

With this mechanism, a certain number of interrupt routines (or other routines) can perform page changes without reading and storing the previously used page information. The use of only write operations makes the system simpler and faster. Consequently, this mechanism significantly improves the performance of short interrupt routines.

The SAL-XC866 supports local address extension for:

- Parallel Ports
- Analog-to-Digital Converter (ADC)
- Capture/Compare Unit 6 (CCU6)
- System Control Registers



The page register has the following definition:

MOD_PAGE

Page Register for module MOD

Reset Value: 00_H

| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|---|---|----|----|---|---|------|---|
| C | P | ST | NR | 0 | | PAGE | |
| ١ | N | V | V | r | • | rw | |

| Field | Bits | Туре | Description |
|-------|-------|------|--|
| PAGE | [2:0] | rw | Page Bits When written, the value indicates the new page. When read, the value indicates the currently active page. |
| STNR | [5:4] | w | Storage NumberThis number indicates which storage bit field is thetarget of the operation defined by bit field OP.If $OP = 10_B$,the contents of PAGE are saved in MOD_STx beforebeing overwritten with the new value.If $OP = 11_B$,the contents of PAGE are overwritten by thecontents of MOD_STx. The value written to the bitpositions of PAGE is ignored.00 MOD_ST0 is selected.01 MOD_ST1 is selected.10 MOD_ST2 is selected.11 MOD_ST3 is selected. |



SAL-XC866

Functional Description

| Field | Bits | Туре | Description | | | | | | |
|-------|-------|------|---|--|--|--|--|--|--|
| OP | [7:6] | w | Operation | | | | | | |
| | | | 0X Manual page mode. The value of STNR is ignored and PAGE is directly written. | | | | | | |
| | | | New page programming with automatic page saving. The value written to the bit positions of PAGE is stored. In parallel, the previous contents of PAGE are saved in the storage bit field MOD_STx indicated by STNR. Automatic restore page action. The value written to the bit positions PAGE is ignored and instead, PAGE is overwritten by the contents of the storage bit field MOD_STx indicated by STNR. | | | | | | |
| 0 | 3 | r | Reserved Returns 0 if read; should be written with 0. | | | | | | |



3.2.3 Bit Protection Scheme

The bit protection scheme prevents direct software writing of selected bits (i.e., protected bits) using the PASSWD register. When the bit field MODE is 11_B , writing 10011_B to the bit field PASS opens access to writing of all protected bits, and writing 10101_B to the bit field PASS closes access to writing of all protected bits. Note that access is opened for maximum 32 CCLKs if the "close access" password is not written. If "open access" password is written again before the end of 32 CCLK cycles, there will be a recount of 32 CCLK cycles. The protected bits include NDIV, WDTEN, PD, and SD.

PASSWD Password Register

Reset Value: 07_H

| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|---|---|------|---|---|---------------|----|----|
| | 1 | PASS | 1 | I | PROTECT _S | мо | DE |
| | | wh | | | rh | ۳۱ | N |

| Field | Bits | Туре | Description |
|-----------|-------|------|---|
| MODE | [1:0] | rw | Bit Protection Scheme Control bits 00 Scheme Disabled 11 Scheme Enabled (default)Others: Scheme EnabledThese two bits cannot be written directly. To changethe value between 11_B and 00_B , the bit field PASSmust be written with 11000_B ; only then, will theMODE[1:0] be registered. |
| PROTECT_S | 2 | rh | Bit Protection Signal Status bitThis bit shows the status of the protection.0Software is able to write to all protected bits.1Software is unable to write to any protected bits. |
| PASS | [7:3] | wh | Password bitsThe Bit Protection Scheme only recognizes three patterns.11000BEnables writing of the bit field MODE.10011BOpens access to writing of all protected bits.10101BCloses access to writing of all protected bits. |



3.2.4 SAL-XC866 Register Overview

The SFRs of the SAL-XC866 are organized into groups according to their functional units. The contents (bits) of the SFRs are summarized in **Table 5** to **Table 13**, with the addresses of the bitaddressable SFRs appearing in bold typeface.

The CPU SFRs can be accessed in both the standard and mapped memory areas (RMAP = 0 or 1).

| Addr | Register Name | | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 | |
|-----------------|---|-----------------------------------|-----------|------------|------------|------------|------------|-------|------|------|-------|--|
| RMAP = | 0 or 1 | | | | 1 | 1 | 1 | 1 | | | | |
| 81 _H | SP | Reset: 07 _H | Bit Field | | | | S | P | | | | |
| | Stack Pointer Register | | Туре | rw | | | | | | | | |
| 82 _H | DPL | Reset: 00 _H | Bit Field | DPL7 | DPL6 | DPL5 | DPL4 | DPL3 | DPL2 | DPL1 | DPL0 | |
| | Data Pointer Register Lov | N | Туре | rw | rw | rw | rw | rw | rw | rw | rw | |
| 83 _H | DPH | Reset: 00 _H | Bit Field | DPH7 | DPH6 | DPH5 | DPH4 | DPH3 | DPH2 | DPH1 | DPH0 | |
| | Data Pointer Register Hig | h | Туре | rw | rw | rw | rw | rw | rw | rw | rw | |
| 87 _H | PCON | Reset: 00 _H | Bit Field | SMOD | | 0 | | GF1 | GF0 | 0 | IDLE | |
| | Power Control Register | | Туре | rw | | r | | rw | rw | r | rw | |
| 88 _H | TCON | Reset: 00 _H | Bit Field | TF1 | TR1 | TF0 | TR0 | IE1 | IT1 | IE0 | IT0 | |
| | Timer Control Register | | Туре | rwh | rw | rwh | rw | rwh | rw | rwh | rw | |
| 89 _H | TMOD | Reset: 00 _H | Bit Field | GATE1 | 0 | Τŕ | 1M | GATE0 | 0 | TC | M | |
| | Timer Mode Register | | Туре | rw | r | rw | | rw | r | r | w | |
| 8A _H | TL0 | Reset: 00 _H | Bit Field | | | | V | 4L | | | | |
| | Timer 0 Register Low | | Туре | rwh | | | | | | | | |
| 8B _H | TL1 | Reset: 00 _H | Bit Field | | | | V | 4L | | | | |
| | Timer 1 Register Low | | Туре | | | | rv | vh | | | | |
| 8C _H | TH0 Reset: 00 _H Timer 0 Register High | | Bit Field | | | | V | 4L | | | | |
| | | | Туре | | | | rv | vh | | | | |
| 8D _H | TH1 Reset: 00 _H | | Bit Field | | | | V | 4L | | | | |
| | Timer 1 Register High | | Туре | | | | rv | vh | | | | |
| 98 _H | SCON | Reset: 00 _H | Bit Field | SM0 | SM1 | SM2 | REN | TB8 | RB8 | TI | RI | |
| | Serial Channel Control R | egister | Туре | rw | rw | rw | rw | rw | rwh | rwh | rwh | |
| 99 _H | SBUF | Reset: 00 _H | Bit Field | VAL | | | | | | | | |
| | Serial Data Buffer Registe | ər | Туре | | | | rv | vh | | | | |
| A2 _H | EO | Reset: 00 _H | Bit Field | | 0 | | TRAP_ | | 0 | | DPSEL | |
| | Extended Operation Regi | ster | | | | | EN | | | | 0 | |
| | | | Туре | | r | | rw | | r | | rw | |
| A8 _H | IEN0 | Reset: 00 _H | Bit Field | EA | 0 | ET2 | ES | ET1 | EX1 | ET0 | EX0 | |
| | | 0 | Туре | rw | r | rw | rw | rw | rw | rw | rw | |
| B8 _H | IP | Reset: 00 _H | Bit Field | | 0 | PT2 | PS | PT1 | PX1 | PT0 | PX0 | |
| | Interrupt Filonity Register | | Туре | | r | rw | rw | rw | rw | rw | rw | |
| B9 _Н | IPH | Reset: 00 _H | Bit Field | | 0 | PT2H | PSH | PT1H | PX1H | PT0H | PX0H | |
| | Interrupt Filonity Register | - Ingri | Туре | | r | rw | rw | rw | rw | rw | rw | |
| D0 _H | PSW Program Status Word Po | Reset: 00 _H | Bit Field | CY | AC | F0 | RS1 | RS0 | OV | F1 | Р | |
| | Filogram Status Word Re | gistei | Туре | rw | rwh | rwh | rw | rw | rwh | rwh | rh | |
| E0 _H | ACC | Reset: 00 _H | Bit Field | ACC7 | ACC6 | ACC5 | ACC4 | ACC3 | ACC2 | ACC1 | ACC0 | |
| | Acculturator Register | | Туре | rw | rw | rw | rw | rw | rw | rw | rw | |
| E8 _H | IEN1 Interrupt Enable Register | Reset: 00_H 1 | Bit Field | ECCIP 3 | ECCIP 2 | ECCIP 1 | ECCIP 0 | EXM | EX2 | ESSC | EADC | |
| | | | Туре | rw | rw | rw | rw | rw | rw | rw | rw | |

Table 5 CPU Register Overview



Table 5 CPU Register Overview (cont'd)

| Addr | Register Name | | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|-----------------|------------------------------------|-------------------------------------|-----------|-------------|-------------|-------------|-------------|------|------|-------|-----------|
| F0 _H | В | Reset: 00 _H | Bit Field | B7 | B6 | B5 | B4 | B3 | B2 | B1 | B0 |
| | B Register | | Туре | rw | rw | rw | rw | rw | rw | rw | rw |
| F8 _H | IP1 Interrupt Priority Registe | Reset: 00 _H er 1 | Bit Field | PCCIP 3 | PCCIP 2 | PCCIP 1 | PCCIP 0 | PXM | PX2 | PSSC | PADC |
| | | | Туре | rw | rw | rw | rw | rw | rw | rw | rw |
| F9 _H | IPH1 Interrupt Priority Registe | Reset: 00 _H er 1 High | Bit Field | PCCIP 3H | PCCIP 2H | PCCIP 1H | PCCIP 0H | PXMH | PX2H | PSSCH | PADC H |
| | | | Туре | rw | rw | rw | rw | rw | rw | rw | rw |

The system control SFRs can be accessed in the standard memory area (RMAP = 0).

Table 6 System Control Register Overview

| Addr | Register Name | | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|-----------------|---|----------------------------------|------------|-----|-------------|--------------|-------------|--------------|---------------|-------------|-------------|
| RMAP = | 0 or 1 | | | 1 | 1 | 1 | | | 1 | | |
| 8F _H | SYSCON0 R | eset: 00 _H | Bit Field | | | | 0 | | | | RMAP |
| | System Control Register 0 | | Туре | | | | r | | | | rw |
| RMAP = | 0 | | 1 | | | | | | | | |
| BF _H | SCU_PAGE R | eset: 00 _H | Bit Field | C |)P | ST | STNR | | | PAGE | |
| | Page Register for System C | ontrol | Туре | , | N | ١ | v | r | | rwh | |
| RMAP = | 0, Page 0 | | | | | | | | | | |
| B3 _H | MODPISEL Regimeration | eset: 00 _H | Bit Field | | 0 | JTAG | JTAG | | 0 | EXINT | URRIS |
| | Periprieral input Select Regi | SIEI | Type | | r | rw | rw | | r | rw | rw |
| B4 | IRCON0 R | eset 00 | Bit Field | 0 | FXINT | EXINT | EXINT | EXINT | FXINT | EXINT | EXINT |
| Ъчн | Interrupt Request Register 0 |) | Dit i loid | Ŭ | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
| | | | Туре | r | rwh | rwh | rwh | rwh | rwh | rwh | rwh |
| B5 _H | IRCON1 Reset: 0 Interrupt Request Register 1 | | Bit Field | 0 | | | ADCS RC1 | ADCS RC0 | RIR | TIR | EIR |
| | | | Туре | r | | | rwh | rwh rwh | | rwh | rwh |
| B7 _H | EXICON0 R | eset: 00 _H | Bit Field | EXI | NT3 | EXI | NT2 | EXI | NT1 | EXI | NT0 |
| | External Interrupt Control Register 0 | | Туре | r | w | r | N | r | w | r | w |
| BA _H | EXICON1 Reset: 00 _H | | Bit Field | | 0 | EXI | NT6 | EXI | NT5 | EXI | NT4 |
| | External Interrupt Control Re | egister 1 | Туре | r | | rw | | rw | | rw | |
| BB _H | NMICON Register | eset: 00 _H | Bit Field | 0 | NMI ECC | NMI VDDP | NMI VDD | NMI OCDS | NMI FLASH | NMI PLL | NMI WDT |
| | | | Туре | r | rw | rw | rw | rw | rw | rw | rw |
| BC _H | NMISR Register | eset: 00 _H | Bit Field | 0 | FNMI ECC | FNMI VDDP | FNMI VDD | FNMI OCDS | FNMI FLASH | FNMI PLL | FNMI WDT |
| | ° ° | | Туре | r | rwh | rwh | rwh | rwh | rwh | rwh | rwh |
| BD _H | BCON R | eset: 00 _H | Bit Field | BG | SEL | 0 | BREN | | BRPRE | 1 | R |
| | Baud Rate Control Register | | Туре | r | w | r | rw | rw | | | rw |
| BE _H | BG R | eset: 00 _H | Bit Field | | | 1 | BR_V | ALUE | | | |
| | Baud Rate Timer/Reload Re | egister | Туре | | | | n | N | | | |
| E9 _H | FDCON R Fractional Divider Control R | eset: 00 _H egister | Bit Field | BGS | SYNEN | ERRSY N | EOFSY N | BRK | NDOV | FDM | FDEN |
| | | | Туре | rw | rw | rwh | rwh | rwh | rwh | rw | rw |
| EA _H | FDSTEP R | eset: 00 _H | Bit Field | | | | ST | EP | | | |
| | Fractional Divider Reload Re | egister | Туре | | | | r\ | N | | | |
| EB _H | FDRES R | eset: 00 _H | Bit Field | | | | RES | ULT | | | |
| | Fractional Divider Result Re | gister | Туре | | | | r | h | | | |
| RMAP = | 0, Page 1 | | | | | | | | | | |



Table 6 System Control Register Overview (cont'd)

| Addr | Register Name | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|-----------------|---|-----------|------------|--------------------------|--------|-----------|------------|--------------------|-------------|--------------|
| B3 _H | ID Reset: 01 _H | Bit Field | | 1 | PRODID |) | 1 | | VERID | 1 |
| | Identity Register | Туре | | | r | | | r | | |
| B4 _H | PMCON0 Reset: 00 _H Power Mode Control Register 0 | Bit Field | 0 | 0 WDT WKRS WK RST SEL | | WK SEL | SD | PD | v | /S |
| | | Туре | r | rwh | rwh | rw | rw | rwh | r | w |
| B5 _H | PMCON1 Reset: 00 _H Power Mode Control Register 1 | Bit Field | | (| 0 | | T2_DIS | CCU _DIS | SSC _DIS | ADC _DIS |
| | | Туре | | r | | | | rw | rw | rw |
| B6 _H | OSC_CON Reset: 08 _H OSC Control Register | Bit Field | | 0 | | OSC PD | XPD | OSC SS | ORD RES | OSCR |
| | | Туре | | r | | rw | rw | rw | rwh | rh |
| В7 _Н | PLL_CON Reset: 20 _H PLL Control Register | Bit Field | | NE | VIV | | VCO BYP | OSC DISC | RESLD | LOCK |
| | | Туре | | rw | | | rw | rw | rwh | rh |
| BA _H | CMCON Reset: 00 _H Clock Control Register | Bit Field | VCO SEL | VCO 0 SEL | | | | CLK | REL | |
| | | Туре | rw | | r | | | r | w | |
| BB _H | PASSWD Reset: 07 _H Password Register | Bit Field | PASS | | | | | PROTE MODE CT_S | | |
| | | Туре | | | w | | | rh rw | | |
| BCH | FEAL Reset: 00 _H | Bit Field | | | E | CCERR | ADDR[7: | 0] | | |
| | Flash Error Address Register Low | Туре | rh | | | | | | | |
| BD _H | FEAH Reset: 00 _H | Bit Field | | | E | CCERRA | ADDR[15 | :8] | | |
| | Flash Error Address Register High | Туре | | | | n | rh | | | |
| BE _H | COCON Reset: 00 _H Clock Output Control Register | Bit Field | | D | TLEN | COUT S | | CO | REL | |
| | | Туре | | r | rw | rw | | r | w | |
| E9 _H | MISC_CON Reset: 00 _H Miscellaneous Control Register | Bit Field | | | | 0 | | | | DFLAS HEN |
| | | Туре | r | | | | | | | rwh |
| RMAP = | 0, Page 3 | | | | | | | | | |
| B3 _H | XADDRH Reset: F0 _H | Bit Field | | | | ADI | DRH | | | |
| | On-Chip XRAM Address Higher Order | Туре | | | | r | w | | | |

The WDT SFRs can be accessed in the mapped memory area (RMAP = 1).

Table 7 WDT Register Overview

| Addr | Register Name | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 | | | |
|-----------------|--|-----------|-----------|---|---|-----------|---|-----------|-----------|-----------|--|--|--|
| RMAP = | 1 | | | | | | | | | | | | |
| BB _H | WDTCON Reset: 00 _H Watchdog Timer Control Register | Bit Field | | 0 | | WDT PR | 0 | WDT EN | WDT RS | WDT IN | | | |
| | | Туре | | r | | rh | r | rw | rwh | rw | | | |
| BC _H | WDTREL Reset: 00 _H | Bit Field | WDTREL | | | | | | | | | | |
| | Watchdog Timer Reload Register | Туре | rw | | | | | | | | | | |
| BD _H | WDTWINB Reset: 00 _H Watchdog Window-Boundary Count | Bit Field | WDTWINB | | | | | | | | | | |
| | Register | Туре | rw | | | | | | | | | | |
| BE _H | WDTL Reset: 00 _H | Bit Field | WDT[7:0] | | | | | | | | | | |
| | Watchdog Timer Register Low | Туре | rh | | | | | | | | | | |
| BF _H | WDTH Reset: 00 _H | Bit Field | WDT[15:8] | | | | | | | | | | |
| | Watchdog Timer Register High | Туре | rh | | | | | | | | | | |



The Port SFRs can be accessed in the standard memory area (RMAP = 0).

Table 8 Port Register Overview

| Addr | Register Name | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|-----------------|--|-------------------|----------|----------|----------|------------|----------|----------|----------|-------|
| RMAP = | 0 | | 1 | | | 1 | | 1 | 1 | |
| B2 _H | PORT_PAGE Reset: 00 _H | Bit Field | C |)P | ST | NR | 0 | | PAGE | |
| | Page Register for PORT | Туре | | w | 1 | N | r | | rwh | |
| RMAP = | 0, Page 0 | | | | | | | • | | |
| 80 _H | P0_DATA Reset: 00 _H | Bit Field | | 0 | P5 | P4 | P3 | P2 | P1 | P0 |
| | P0 Data Register | Туре | | r | rwh | rwh | rwh | rwh | rwh | rwh |
| 86 _H | P0_DIR Reset: 00 _H | Bit Field | | 0 | P5 | P4 | P3 | P2 | P1 | P0 |
| | P0 Direction Register | Туре | | r | rw | rw | rw | rw | rw | rw |
| 90 _H | P1_DATA Reset: 00 _H | Bit Field | P7 | P6 | P5 | | 0 | | P1 | P0 |
| | P1 Data Register | Туре | rwh | rwh | rwh | | r | | rwh | rwh |
| 91 _H | P1_DIR Reset: 00 _H | Bit Field | P7 | P6 | P5 | | 0 | P1 | | P0 |
| | P1 Direction Register | Туре | rw | rw | rw | | r | | rw | rw |
| A0 _H | P2_DATA Reset: 00 _H | Bit Field | P7 | P6 | P5 | P4 | P3 | P2 | P1 | P0 |
| | P2 Data Register | Туре | rwh | rwh | rwh | rwh | rwh | rwh | rwh | rwh |
| А1 _Н | P2_DIR Reset: 00 _H | Bit Field | P7 | P6 | P5 | P4 | P3 | P2 | P1 | P0 |
| | P2 Direction Register | Туре | rw | rw | rw | rw | rw | rw | rw | rw |
| В0 _Н | P3_DATA Reset: 00 _H | Bit Field | P7 | P6 | P5 | P4 | P3 | P2 | P1 | P0 |
| | P3 Data Register | Туре | rwh | rwh | rwh | rwh | rwh | rwh | rwh | rwh |
| B1 _H | P3_DIR Reset: 00 _H | Bit Field | P7 | P6 | P5 | P4 | P3 | P2 | P1 | P0 |
| | P3 Direction Register | Туре | rw | rw | rw | rw | rw | rw | rw | rw |
| RMAP = | 0, Page 1 | | | - | _ | _ | _ | _ | _ | - |
| 80 _H | P0_PUDSEL Reset: FF _H | Bit Field | | 0 | P5 | P4 | P3 | P2 | P1 | P0 |
| | FO Full-Op/Full-Down Select Register | Туре | | r | rw | rw | rw | rw | rw | rw |
| 86 _H | 6 _H P0_PUDEN Reset: C4 _H | Bit Field | | 0 | P5 | 5 P4 P3 P2 | | P2 | P1 | P0 |
| | POPuli-Op/Puli-Down Enable Register | Туре | | r | rw | rw | rw | rw | rw | rw |
| 90 _H | P1_PUDSEL Reset: FF _H P1 Pull-I lp/Pull-Down Select Register | Bit Field | P7 | P6 | P5 | | 0 | | P1 | PO |
| | | l ype | rw | rw | rw | | r | | rw | rw |
| 91 _H | P1_PUDEN Reset: FF _H P1 Pull-I Ip/Pull-Down Enable Register | Bit Field | P7 | P6 | P5 | | 0 | | | P0 |
| | | Type | rw | rw | rw | D 4 | r | DO | rw D1 | rw |
| A0 _H | P2_PUDSEL Reset: FF _H P2 Pull-Llp/Pull-Down Select Register | Bit Field | Ρ/ | P6 | P5 | P4 | P3 | P2 | P1 | P0 |
| | | Type | rw D7 | rw | rw DC | rw D4 | rw | rw | rw D4 | rw |
| A1 _H | P2_PUDEN Reset: 00 _H P2 Pull-I In/Pull-Down Enable Register | Bit Fleid | P7 | P6 | P5 | P4 | P3 | P2 | P1 | PU |
| BO | | Type Dit Field | rw D7 | rw DC | rw DC | rw D4 | rw D2 | rw D2 | rw D1 | rw |
| БОН | P3 Pull-Up/Pull-Down Select Register | Bit Field | P7 | P6 | P5 | P4 | P3 | P2 | PI | PU |
| D4 | | Type Dit Field | | TW DC | TW DE | TW D4 | IW D2 | IW DO | TW D4 | TW DO |
| ын | P3 Pull-Up/Pull-Down Enable Register | Bit Field | P7 | Po | P5 | P4 | P3 | P2 | PI | PU |
| | 0. Rogo 2 | туре | TW | IW | IW | IW | TW | T VV | T VV | IW |
| | | Dit Field | | 0 | DE | D4 | D2 | D2 | D1 | DO |
| ου _Η | P0 Alternate Select 0 Register | Dit Field | | 0 r | FU | F4 | FO | F2 | F I | FU |
| 96 | P0_ALTSEL1 Posot: 00 | Rit Field | | 0 | P5 | D/ | D2 | P2 | D1 | P0 |
| 90 ^H | P0 Alternate Select 1 Register | | | r | F3 | F4 | FJ | F2 | | FU |
| 00. | P1 ALTSELO Resot: 00 | Rit Field | P7 | P6 | P5 | TVV | 0 | 1 00 | P1 | PO |
| 30H | P1 Alternate Select 0 Register | Type | F7 | FU | F J | | r | | F I | F U |
| Q1 | P1 ALTSEL1 Reset: 00 | Rit Field | P7 | P6 | P5 | | 0 | | P1 | PO |
| a H | P1 Alternate Select 1 Register | Type | F/ | FU DW | FJ PM | | r | | F I | PW |
| B0 | P3 ALTSELO Reset: 00 | Rit Field | P7 | P6 | P5 | P4 | P3 | P2 | P1 | PO |
| DOH | P3 Alternate Select 0 Register | Type | DW. | TW | nw. | rw | 1.0 | 12 | FW/ | rw. |
| 1 | U | 1,100 | | 1 44 | 1.44 | 1 4 4 | 1 44 | 1 44 | 1 4 4 | 1 4 4 |



Table 8 Port Register Overview (cont'd)

| Addr | Register Name | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|-----------------|--|-----------|----|----|----|----|----|----|----|----|
| B1 _H | P3_ALTSEL1 Reset: 00 _H | Bit Field | P7 | P6 | P5 | P4 | P3 | P2 | P1 | P0 |
| | P3 Alternate Select 1 Register | Туре | rw |
| RMAP = | 0, Page 3 | | | | | | | | | |
| 80 _H | P0_OD Reset: 00 _H P0 Open Drain Control Register | Bit Field | | D | P5 | P4 | P3 | P2 | P1 | P0 |
| | | Туре | | r | rw | rw | rw | rw | rw | rw |
| 90 _H | P1_OD Reset: 00 _H P1 Open Drain Control Register | Bit Field | P7 | P6 | P5 | 0 | | | P1 | P0 |
| | | Туре | rw | rw | rw | | r | rw | rw | |
| B0 _H | P3_OD Reset: 00 _H | Bit Field | P7 | P6 | P5 | P4 | P3 | P2 | P1 | P0 |
| | P3 Open Drain Control Register | Туре | rw |

The ADC SFRs can be accessed in the standard memory area (RMAP = 0).

Table 9 ADC Register Overview

| Addr | Register Name | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 | |
|-----------------|--|-------------|------------|--------------------|-------|------|-----------|-------|------------|-------|--|
| RMAP = | 0 | | | | | 1 | | 1 | 1 | 1 | |
| D1 _H | ADC_PAGE Reset: 00 | H Bit Field | C |)P | ST | NR | 0 | PAGE | | | |
| | Page Register for ADC | Туре | , | w | ١ | N | r | | rwh | | |
| RMAP = | 0, Page 0 | • | | | | | | | | | |
| CA _H | ADC_GLOBCTR Reset: 30 | H Bit Field | ANON | DW | C | тс | | |) | | |
| | Global Control Register | Туре | rw | rw | r | w | | | r | | |
| CBH | ADC_GLOBSTR Reset: 00 Global Status Register | H Bit Field | | 0 | | CHNR | | 0 | SAM PLE | BUSY | |
| | | Туре | | r | | rh | | r | rh | rh | |
| CCH | ADC_PRAR Reset: 00 | H Bit Field | ASEN1 | ASEN0 | 0 | ARBM | CSM1 | PRIO1 | CSM0 | PRIO0 | |
| | Priority and Arbitration Register | Туре | rw | rw | r | rw | rw | rw | rw | rw | |
| CD _H | ADC_LCBR Reset: B7 | H Bit Field | | BOU | IND1 | | | BOL | JND0 | | |
| | Limit Check Boundary Register | Туре | | r | w | | | r | w | | |
| CEH | ADC_INPCR0 Reset: 00 | H Bit Field | STC | | | | | | | | |
| | Input Class Register 0 | Туре | | rw | | | | | | | |
| CF _H | ADC_ETRCR Reset: 00 External Trigger Control Register | H Bit Field | SYNEN 1 | SYNEN SYNEN ETRSEL | | | 1 ETRSEL0 | | | | |
| | | Туре | rw | rw | rw rw | | rw | | | | |
| RMAP = | 0, Page 1 | | | | | | | | | | |
| CA _H | ADC_CHCTR0 Reset: 00 | H Bit Field | 0 | LCC | | 0 | | RES | RSEL | | |
| | Channel Control Register 0 | Туре | r | | rw | | r | | rw | | |
| CBH | ADC_CHCTR1 Reset: 00 | H Bit Field | 0 | | LCC | | 0 | | RESRSEL | | |
| | Channel Control Register 1 | Туре | r | | rw | | r | | rw | | |
| CCH | ADC_CHCTR2 Reset: 00 | H Bit Field | 0 | | LCC | | | 0 | RESRSEL | | |
| | Channel Control Register 2 | Туре | r | | rw | | | r | rw | | |
| CD _H | ADC_CHCTR3 Reset: 00 | H Bit Field | 0 | | LCC | | | 0 | RESRSEL | | |
| | Channel Control Register 3 | Туре | r | | rw | | | r | rw | | |
| CEH | ADC_CHCTR4 Reset: 00 | H Bit Field | 0 | | LCC | | | 0 | RES | RSEL | |
| | Channel Control Register 4 | Туре | r | | rw | | | r | r | w | |
| CF _H | ADC_CHCTR5 Reset: 00 | H Bit Field | 0 | | LCC | | | 0 | RES | RSEL | |
| | Channel Control Register 5 | Туре | r | | rw | | | r | r | w | |
| D2 _H | ADC_CHCTR6 Reset: 00 | H Bit Field | 0 | | LCC | | | 0 | RES | RSEL | |
| | Channel Control Register 6 | Туре | r | r rw | | | r | | rw | | |
| D3 _H | ADC_CHCTR7 Reset: 00 | H Bit Field | 0 | | LCC | | 0 | | RES | RSEL | |
| | Channel Control Register 7 | Туре | r | | rw | | | r | r | w | |
| RMAP = | 0, Page 2 | | | | | | | | | | |

Data Sheet



Table 9 ADC Register Overview (cont'd)

| Addr | Register Name | | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 0 | | | |
|-----------------|---------------------------------------|--------------------------------|-----------|----------------|---------|-----|-------|----------|---|--|-----------|--|--|
| CA _H | ADC_RESR0L | Reset: 00 _H | Bit Field | RESU | LT[1:0] | 0 | VF | DRC CHNR | | | | | |
| | Result Register 0 Low | | Туре | r | h | r | rh | rh | | | | | |
| CBH | ADC_RESR0H | Reset: 00 _H | Bit Field | | | | RESU | LT[9:2] | | | | | |
| | Result Register 0 High | | Туре | | rh | | | | | | | | |
| CCH | ADC_RESR1L | Reset: 00 _H | Bit Field | RESU | LT[1:0] | 0 | VF | DRC | | | | | |
| | Result Register 1 Low | | Туре | r | h | r | rh | rh | | rh | | | |
| CD _H | ADC_RESR1H | Reset: 00 _H | Bit Field | | | | RESU | LT[9:2] | 1 | | | | |
| | Result Register 1 High | | Туре | | | | r | 'n | | | | | |
| CEH | ADC_RESR2L | Reset: 00 _H | Bit Field | RESU | LT[1:0] | 0 | VF | DRC | | CHNR | | | |
| | Result Register 2 Low | | Туре | r | h | r | rh | rh | | rh | | | |
| CF _H | ADC_RESR2H | Reset: 00 _H | Bit Field | | | | RESU | LT[9:2] | | | | | |
| | Result Register 2 High | | Туре | | | | r | h | 2 1 C CHNR i rh 2] CHNR i rh 2] rh C CHNR i rh 2] rh C CHNR i rh 2] rh C CHNR i rh 3] rh G CHNR i rh 3] | | | | |
| D2 _H | ADC_RESR3L | Reset: 00 _H | Bit Field | RESU | LT[1:0] | 0 | VF | DRC | | CHNR | | | |
| | Result Register 3 Low | | Туре | r | h | r | rh | rh | | rh | | | |
| D3 _H | ADC_RESR3H | Reset: 00 _H | Bit Field | | | | RESU | LT[9:2] | | 2 1 CHNR rh CHNR | | | |
| | Result Register 3 High | | Туре | | | | r | h | | CHNR | | | |
| RMAP = | 0, Page 3 | | | | | | | | | | | | |
| CA _H | ADC_RESRA0L | Reset: 00 _H | Bit Field | R | ESULT[2 | :0] | VF | DRC | | CHNR | | | |
| | Result Register 0, View A | Low | Туре | | rh | | rh | rh | | rh | | | |
| CBH | ADC_RESRA0H | RESRA0H Reset: 00 _H | | RESULT[10:3] | | | | | | | | | |
| | Result Register 0, View A High | | | | | | r | h | | | | | |
| CCH | CC _H ADC_RESRA1L Res | | Bit Field | R | ESULT[2 | :0] | VF | DRC | | CHNR | | | |
| | Result Register 1, View A Low | | Туре | | rh | | rh | rh | | rh | | | |
| CD _H | ADC_RESRA1H Reset: 00 _H | | Bit Field | | | | RESUL | T[10:3] | | | | | |
| | Result Register 1, View A | \ High | Туре | rh | | | | | | | | | |
| CEH | ADC_RESRA2L | Reset: 00 _H | Bit Field | RESULT[2:0] VF | | | | DRC | | CHNR | | | |
| | Result Register 2, View A | Low | Туре | | rh | | rh | rh | | | | | |
| CF _H | ADC_RESRA2H | Reset: 00 _H | Bit Field | | | | RESUL | LT[10:3] | | | | | |
| | Result Register 2, View A | A High | Туре | | | | r | h | | | | | |
| D2 _H | ADC_RESRA3L | Reset: 00 _H | Bit Field | RE | SULT[2 | :0] | VF | DRC | rh CHNR rh < | | | | |
| | Result Register 3, View A | Low | Туре | | rh | | rh | rh | | rh | | | |
| D3 _H | ADC_RESRA3H | Reset: 00 _H | Bit Field | | | | RESUL | T[10:3] | | | | | |
| | Result Register 3, View A | \ High | Туре | | | | r | h | | | | | |
| RMAP = | 0, Page 4 | | | | | | | | | | | | |
| CA _H | ADC_RCR0 Result Control Register 0 | Reset: 00 _H | Bit Field | VFCTR | WFR | 0 | IEN | | 0 | | DRCT R | | |
| | | | Туре | rw | rw | r | rw | | r | | rw | | |
| СВ _Н | ADC_RCR1 Result Control Register 1 | Reset: 00 _H | Bit Field | VFCTR | WFR | 0 | IEN | | 0 | | DRCT R | | |
| | | | Туре | rw | rw | r | rw | | r | | rw | | |
| CC _H | ADC_RCR2 Result Control Register 2 | Reset: 00 _H | Bit Field | VFCTR | WFR | 0 | IEN | | 0 | | DRCT R | | |
| | | | Туре | rw | rw | r | rw | | r | | rw | | |
| CD _H | ADC_RCR3 Result Control Register 3 | Reset: 00 _H | Bit Field | VFCTR | WFR | 0 | IEN | | 0 | | DRCT R | | |
| L | | | Туре | rw | rw | r | rw | | r | | rw | | |
| CEH | ADC_VFCR | Reset: 00 _H | Bit Field | | |) | | VFC3 | VFC2 | VFC1 | VFC0 | | |
| L | valid Flag Clear Register | | Туре | | | r | | w | w | w | W | | |
| RMAP = | 0, Page 5 | | | | | | | | | | | | |



Table 9 ADC Register Overview (cont'd)

| Addr | Register Name | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 | |
|--|--|-----------|------------|------------|------------|------------|------------|------------|------------|------------|--|
| CA _H | ADC_CHINFR Reset: 00 _H Channel Interrupt Flag Register | Bit Field | CHINF 7 | CHINF 6 | CHINF 5 | CHINF 4 | CHINF 3 | CHINF 2 | CHINF 1 | CHINF 0 | |
| | | Туре | rh | |
| СВ _Н | ADC_CHINCR Reset: 00 _H Channel Interrupt Clear Register | Bit Field | CHINC 7 | CHINC 6 | CHINC 5 | CHINC 4 | CHINC 3 | CHINC 2 | CHINC 1 | CHINC 0 | |
| | | Туре | w | w | w | w | w | w | w | w | |
| CCH | ADC_CHINSR Reset: 00 _H Channel Interrupt Set Register | Bit Field | CHINS 7 | CHINS 6 | CHINS 5 | CHINS 4 | CHINS 3 | CHINS 2 | CHINS 1 | CHINS 0 | |
| | | Туре | w | w | w | w | w | w | w | w | |
| CD _H | ADC_CHINPR Reset: 00 _H Channel Interrupt Node Pointer | Bit Field | CHINP 7 | CHINP 6 | CHINP 5 | CHINP 4 | CHINP 3 | CHINP 2 | CHINP 1 | CHINP 0 | |
| | Register | Туре | rw | |
| CEH | ADC_EVINFR Reset: 00 _H Event Interrupt Flag Register | Bit Field | EVINF 7 | EVINF 6 | EVINF 5 | EVINF 4 | (| D | EVINF 1 | EVINF 0 | |
| | | Туре | rh | rh | rh | rh | | r | rh | rh | |
| CF _H | ADC_EVINCR Reset: 00 _H Event Interrupt Clear Flag Register | Bit Field | EVINC 7 | EVINC 6 | EVINC 5 | EVINC 4 | (| D | EVINC 1 | EVINC 0 | |
| | | Туре | w | w | w | w | r | | w | w | |
| D2 _H ADC_EVINSR Event Interrupt Se | ADC_EVINSR Reset: 00 _H Event Interrupt Set Flag Register | Bit Field | EVINS 7 | EVINS 6 | EVINS 5 | EVINS 4 | 0 | | EVINS 1 | EVINS 0 | |
| | | Туре | w | w | w | w | | r | w | w | |
| D3 _H | ADC_EVINPR Reset: 00 _H Event Interrupt Node Pointer Register | Bit Field | EVINP 7 | EVINP 6 | EVINP 5 | EVINP 4 | 0 | | EVINP 1 | EVINP 0 | |
| | | Туре | rw | rw | rw | rw | r | | rw | rw | |
| RMAP = | 0, Page 6 | | | | | | | | | | |
| CA _H | ADC_CRCR1 Reset: 00 _H Conversion Request Control Register 1 | Bit Field | CH7 | CH6 | CH5 | CH4 | 0 | | | | |
| | | Туре | rwh | rwh | rwh | rwh | r | | | | |
| СВ _Н | ADC_CRPR1 Reset: 00 _H Conversion Request Pending | Bit Field | CHP7 | CHP6 | CHP5 | CHP4 | | (|) | | |
| | Register 1 | Туре | rwh | rwh | rwh | rwh | | | r | | |
| CC _H | ADC_CRMR1 Reset: 00 _H Conversion Request Mode Register 1 | Bit Field | Rsv | LDEV | CLR PND | SCAN | ENSI | ENTR | EN | GT | |
| | | Туре | r | w | w | rw | rw | rw | r | w | |
| CD _H | ADC_QMR0 Reset: 00 _H | Bit Field | CEV | TREV | FLUSH | CLRV | TRMD | ENTR | EN | IGT | |
| | Queue Mode Register 0 | Туре | w | w | w | w | rw | rw | r | w | |
| CEH | ADC_QSR0 Reset: 20 _H | Bit Field | Rsv | 0 | EMPTY | EV | | (|) | | |
| | | Туре | r | r | rh | rh | _ | r | | _ | |
| CF _H | ADC_Q0R0 Reset: 00 _H | Bit Field | EXTR | ENSI | RF | V | 0 | REQCHNR | | R | |
| | | Туре | rh | rh | rh | rh | r | _ | rh | _ | |
| 02 _H | ADC_QBUR0 Reset: 00 _H | Bit Field | EXTR | ENSI | RF | V | 0 | R | LQCHN | R | |
| | | Туре | rh | rh | rh | rh | r | rh | | - | |
| 02 _H | ADC_QINR0 Reset: 00 _H | Bit Field | EXIR | ENSI | RF | (| J | REQCHNR | | к | |
| | Queue input ivegister u | туре | w | w | w | | r | | w | V | |

The Timer 2 SFRs can be accessed in the standard memory area (RMAP = 0).

Table 10Timer 2 Register Overview

| Addr | Register Name | | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|-----------------|--------------------------------------|------------------------|-----------|-----|------|---|---|-------|-----|---|------------|
| С0 _Н | T2_T2CON Timer 2 Control Register | Reset: 00 _H | Bit Field | TF2 | EXF2 | | 0 | EXEN2 | TR2 | 0 | CP/ RL2 |
| | | | Туре | rwh | rwh | | r | rw | rwh | r | rw |


Table 10 Timer 2 Register Overview (cont'd)

| C1 _H | T2_T2MOD Timer 2 Mode Register | Reset: 00 _H | Bit Field | T2 REGS | T2 RHEN | EDGE SEL | PREN | T2PRE | DCEN |
|-----------------|-----------------------------------|------------------------|-----------|------------|------------|-------------|------|--------|------|
| | | | Туре | rw | rw | rw | rw | rw | rw |
| C2 _H | T2_RC2L | Reset: 00 _H | Bit Field | | | | RC2 | [7:0] | |
| | Timer 2 Reload/Capture | Register Low | Туре | | | | rv | /h | |
| C3 _H | T2_RC2H | Reset: 00 _H | Bit Field | | | | RC2[| 15:8] | |
| | Timer 2 Reload/Capture | Register High | Туре | | | | rv | /h | |
| C4 _H | T2_T2L | Reset: 00 _H | Bit Field | | | | THL2 | 2[7:0] | |
| | Timer 2 Register Low | | Туре | | | | rv | /h | |
| C5 _H | T2_T2H | Reset: 00 _H | Bit Field | | | | THL2 | [15:8] | |
| | Timer 2 Register High | | Туре | | | | rv | /h | |

The CCU6 SFRs can be accessed in the standard memory area (RMAP = 0).

Table 11 CCU6 Register Overview

| Addr | Register Name | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|-----------------|--|-----------|------------|------------|------------|------------|------------|------------|------------|------------|
| RMAP = | 0 | | 1 | | | | | | | |
| A3 _H | CCU6_PAGE Reset: 00 _H | Bit Field | C | P | ST | NR | 0 | | PAGE | |
| | Page Register for CCU6 | Туре | ١ | N | ١ | v | r | | rwh | |
| RMAP = | 0, Page 0 | | | | | | | | | |
| 9A _H | CCU6_CC63SRL Reset: 00 _H Capture/Compare Shadow Register for | Bit Field | | | | CC6 | 3SL | | | |
| | Channel CC63 Low | Туре | | | | r | w | | | |
| 9B _H | CCU6_CC63SRH Reset: 00 _H Capture/Compare Shadow Register for | Bit Field | | | | CCE | 3SH | | | |
| | Channel CC63 High | Туре | | | | r | w | | | |
| 9C _H | CCU6_TCTR4L Reset: 00 _H Timer Control Register 4 Low | Bit Field | T12 STD | T12 STR | (|) | DTRES | T12 RES | T12RS | T12RR |
| | | Туре | w | w | | r | w | w | w | w |
| 9D _H | CCU6_TCTR4H Reset: 00 _H Timer Control Register 4 High | Bit Field | T13 STD | T13 STR | | 0 | | T13 RES | T13RS | T13RR |
| | | Туре | w | w | r w | | | w | w | |
| 9E _H | CCU6_MCMOUTSL Reset: 00 _H Multi-Channel Mode Output Shadow | Bit Field | STRM CM | 0 | | | MCI | MPS | | |
| | Register Low | Туре | w | r | | | r | w | | |
| 9F _H | CCU6_MCMOUTSH Reset: 00 _H | Bit Field | STRHP | 0 | | CURHS | | EXPHS | | |
| | Multi-Channel Mode Output Shadow Register High | Туре | w | r | | rw | | | rw | |
| A4 _H | CCU6_ISRL Reset: 00 _H Capture/Compare Interrupt Status | Bit Field | RT12P M | RT12O M | RCC62 F | RCC62 R | RCC61 F | RCC61 R | RCC60 F | RCC60 R |
| | Reset Register Low | Туре | w | w | w | w | w | w | w | w |
| A5 _H | CCU6_ISRH Reset: 00 _H Capture/Compare Interrupt Status | Bit Field | RSTR | RIDLE | RWHE | RCHE | 0 | RTRPF | RT13 PM | RT13 CM |
| | Reset Register High | Туре | w | w | w | w | r | w | w | w |
| A6 _H | CCU6_CMPMODIFL Reset: 00 _H Compare State Modification Register | Bit Field | 0 | MCC63 S | | 0 | | MCC62 S | MCC61 S | MCC60 S |
| | Low | Туре | r | w | | r | | w | w | w |
| A7 _H | CCU6_CMPMODIFH Reset: 00 _H Compare State Modification Register | Bit Field | 0 | MCC63 R | | 0 | | MCC62 R | MCC61 R | MCC60 R |
| | High | Туре | r | w | | r | | w | w | w |
| FA _H | CCU6_CC60SRL Reset: 00 _H Capture/Compare Shadow Register for | Bit Field | | | | CC6 | OSL | | | |
| | Channel CC60 Low | Туре | | | | rv | vh | | | |



Table 11 CCU6 Register Overview (cont'd)

| Addr | Register Name | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|-----------------|---|-------------------|---------------|------|-------|-----------|--------------|------|--------|------|
| FB _H | CCU6_CC60SRH Reset: 00 _H Capture/Compare Shadow Register for | Bit Field | | | 1 | CC6 | OSH | | | |
| | Channel CC60 High | Туре | | | | rv | vh | | | |
| FC _H | CCU6_CC61SRL Reset: 00 _H Capture/Compare Shadow Register for | Bit Field | | | | CCE | 51SL | | | |
| | Channel CC61 Low | Туре | | | | rv | vh | | | |
| FD _H | CCU6_CC61SRH Reset: 00 _H Capture/Compare Shadow Register for | Bit Field | | | | CC6 | 1SH | | | |
| | Channel CC61 High | Туре | | | | rv | vh | | | |
| FE _H | CCU6_CC62SRL Reset: 00 _H Capture/Compare Shadow Register for | Bit Field | | | | CCE | S2SL | | | |
| | Channel CC62 Low | Туре | rwh | | | | | | | |
| FF _H | CCU6_CC62SRH Reset: 00 _H Capture/Compare Shadow Register for | Bit Field | | | | CC6 | 2SH | | | |
| | | Туре | | | | rv | vh | | | |
| RMAP = | - 0, Page 1 | | | | | | | | | |
| 9A _H | CC06_CC63RL Reset: 00 _H Capture/Compare Register for Channel | Bit Field | | | | CCE | 53VL | | | |
| | | Type | | | | r | h | | | |
| 9BH | CCU6_CC63RH Reset: 00 _H Capture/Compare Register for Channel | Bit Field | | | | CC6 | 3VH | | | |
| | | Туре | | | | r | h | | | |
| 9CH | CCU6_T12PRL Reset: 00 _H | Bit Field | | | | 112 | PVL | | | |
| | | Type | | | | rv | vh | | | |
| 9DH | Timer T12 Period Register High | Bit Field | | | | 112 | PVH | | | |
| 05 | | Type Dit Field | | | | rv T10 | vn DV/I | | | |
| 9EH | Timer T13 Period Register Low | DIL FIEIO | | | | 113 | PVL | | | |
| 0E. | CCUE T13PPH Posot: 00 | Type Bit Fiold | | | | T12 | | | | |
| 31 H | Timer T13 Period Register High | | | | | 113 | r vi i vh | | | |
| Δ4 | CCU6 T12DTCI Reset: 00 | Bit Field | | | | | ΓM | | | |
| н | Dead-Time Control Register for Timer T12 Low | Туре | | | | r | w | | | |
| A5 _H | CCU6_T12DTCH Reset: 00 _H Dead-Time Control Register for Timer | Bit Field | 0 | DTR2 | DTR1 | DTR0 | 0 | DTE2 | DTE1 | DTE0 |
| | T12 High | Туре | r | rh | rh | rh | r | rw | rw | rw |
| A6 _H | CCU6_TCTR0L Reset: 00 _H Timer Control Register 0 Low | Bit Field | СТМ | CDIR | STE12 | T12R | T12 PRE | | T12CLK | |
| | | Туре | rw | rh | rh | rh | rw | | rw | |
| A7 _H | CCU6_TCTR0H Reset: 00 _H Timer Control Register 0 High | Bit Field | (|) | STE13 | T13R | T13 PRE | | T13CLK | |
| | | Туре | r rh rh rw rw | | | | | | | |
| FA _H | CCU6_CC60RL Reset: 00 _H Capture/Compare Register for Channel | Bit Field | d CC60VL | | | | | | | |
| CC60 Low | | Туре | | | | r | h | | | |
| FB _H | CCU6_CC60RH Reset: 00 _H Capture/Compare Register for Channel | Bit Field | Field CC60VH | | | | | | | |
| | CC60 High | | | | | r | h | | | |
| FC _H | CCU6_CC61RL Reset: 00 _H Capture/Compare Register for Channel | Bit Field | | | | CCE | 51VL | | | |
| | CC61 Low | Туре | | | | r | h | | | |



Table 11 CCU6 Register Overview (cont'd)

| Addr | Register Name | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 | | |
|-----------------|---|-------------------|-------------|-------------|-------------|-------------|-------------|-------------|-------------|-------------|--|--|
| FD _H | CCU6_CC61RH Reset: 00 _H Capture/Compare Register for Channel | Bit Field | | <u> </u> | 1 | CC6 | 51VH | 1 | 1 | I | | |
| | CC61 High | Туре | | | | r | h | | | | | |
| FE _H | CCU6_CC62RL Reset: 00 _H Capture/Compare Register for Channel | Bit Field | | | | CC6 | 32VL | | | | | |
| | CC62 Low | Туре | | | | r | h | | | | | |
| FF _H | CCU6_CC62RH Reset: 00 _H Capture/Compare Register for Channel | Bit Field | | | | CCE | 32VH | | | | | |
| | CC82 High | Туре | | | | r | 'n | | | | | |
| RMAP = | : 0, Page 2 | | 1 | | | | | | | | | |
| 9A _H | CCU6_T12MSELL Reset: 00 _H T12 Capture/Compare Mode Select Register Low | Bit Field | | MSE | =L61 | | | MS | =L60 | | | |
| | | Туре | | r | W | | | r | w | | | |
| 98 _H | CCU6_T12MSELH Reset: 00 _H T12 Capture/Compare Mode Select | Bit Field | DBYP | | HSYNC | | | MSE | EL62 | | | |
| | Register High | Туре | rw | | rw | | | rw | | | | |
| 9C _H | CCU6_IENL Reset: 00 _H Capture/Compare Interrupt Enable | Bit Field | ENT12 PM | ENT12 OM | ENCC 62F | ENCC 62R | ENCC 61F | ENCC 61R | ENCC 60F | ENCC 60R | | |
| | Register Low | Туре | rw | | |
| 9D _H | CCU6_IENH Reset: 00 _H Capture/Compare Interrupt Enable | Bit Field | ENSTR | EN IDLE | EN WHE | EN CHE | 0 | EN TRPF | ENT13 PM | ENT13 CM | | |
| | Register High | Туре | rw | rw | rw | rw | r | rw | rw | rw | | |
| 9E _H | CCU6_INPL Reset: 40 _H Capture/Compare Interrupt Node | Bit Field | INP | CHE | INPO | CC62 | INPO | CC61 | INPO | CC60 | | |
| | Pointer Register Low | Туре | r | w | r | w | r | w | r | w | | |
| 9F _H | CCU6_INPH Reset: 39 _H Capture/Compare Interrupt Node | Bit Field | 1 | 0 | INP | T13 | INP | PT12 | INP | ERR | | |
| | Pointer Register High | Туре | | r | r | w | r | w | rw | | | |
| A4 _H | CCU6_ISSL Reset: 00 _H Capture/Compare Interrupt Status Set | Bit Field | ST12P M | ST12O M | SCC62 F | SCC62 R | SCC61 F | SCC61 R | SCC60 F | SCC60 R | | |
| | Register Low | Туре | w | w | w | w | w | w | w | w | | |
| A5 _H | CCU6_ISSH Reset: 00 _H Capture/Compare Interrupt Status Set | Bit Field | SSTR | SIDLE | SWHE | SCHE | SWHC | STRPF | ST13 PM | ST13 CM | | |
| | | Туре | w | w | w | w | w | w | w | w | | |
| A6 _H | CCU6_PSLR Reset: 00 _H | Bit Field | PSL63 | 0 | | | P | SL | | | | |
| | | Type | rwh | r | 014 | 0.41 | rv | wh | 014/051 | | | |
| A7 _H | Multi-Channel Mode Control Register | Bit Field | |) | SW | SYN | 0 | | SWSEL | | | |
| F 4 | | Type | _ | r T40 | | w | r T40TEC | | rw T40 | T40 | | |
| FAH | Timer Control Register 2 Low | Bit Field | 0 | 113 | TED | | TISTEC | • | SSC | SSC | | |
| 50 | | Type Dit Field | r | r r | w | | rw T40 | | T4 OF | rw DOCL | | |
| FВH | Timer Control Register 2 High | BIT FIEID | | (| 0 | T13RSEL T1 | | 1121 | KSEL | | | |
| 50 | | Type Dit Field | MC | 0 | | | r | w | | | | |
| FCH | Modulation Control Register Low | BITFIEID | MEN | 0 | TIZMUDEN | | | | | | | |
| | | i ype | rw | r | | | | | | | | |
| гD _Н | Modulation Control Register High | Bit Field | 0 | 0 | T13MODEN | | | | | | | |
| L | | | rw | r | | | r | w | | | | |
| FEH | Tran Control Register Low | Bit Field | | | 0 | | | TRPM2 | IRPM1 | IRPM0 | | |
| | Trap Control Register Low | l ype | 1 | | r | | | rw | rw | rw | | |



Table 11 CCU6 Register Overview (cont'd)

| Addr | Register Name | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|-----------------|---|-----------|------------|--------------|--------------|--------------|--------------|------------|--------------|------------|
| FF _H | CCU6_TRPCTRH Reset: 00 _H Trap Control Register High | Bit Field | TRPPE N | TRPEN 13 | | | TR | PEN | | |
| | | Туре | rw | rw | rw | | | | | |
| RMAP = | 0, Page 3 | | | | | | | | | |
| 9A _H | CCU6_MCMOUTL Reset: 00 _H Multi-Channel Mode Output Register | Bit Field | 0 | R | | | MC | MP | | |
| | Low | Туре | r | rh | | | r | h | | |
| 9B _H | CCU6_MCMOUTH Reset: 00 _H Multi-Channel Mode Output Register | Bit Field | | 0 | | CURH | | | EXPH | |
| | High | | | r | | rh | | | rh | |
| 9C _H | CCU6_ISL Reset: 00 _H Capture/Compare Interrupt Status | Bit Field | T12PM | T12OM | ICC62F | ICC62 R | ICC61F | ICC61 R | ICC60F | ICC60 R |
| | Register Low | Туре | rh | rh | rh | rh | rh | rh | rh | rh |
| 9D _H | CCU6_ISH Reset: 00 _H Capture/Compare Interrupt Status | Bit Field | STR | IDLE | WHE | CHE | TRPS | TRPF | T13PM | T13CM |
| | Register High | Туре | rh | rh | rh | rh | rh | rh | rh | rh |
| 9E _H | CCU6_PISEL0L Reset: 00 _H | Bit Field | IST | RP | ISC | ISCC62 ISCC6 | | | ISC | C60 |
| | Port Input Select Register 0 Low | Туре | r | w | n | w | r | w | rw | |
| 9F _H | CCU6_PISEL0H Reset: 00 _H Port Input Select Register 0 High | Bit Field | IST1 | 2HR | ISP | ISPOS2 IS | | POS1 ISP | | OS0 |
| | | Туре | r | w | n | w | r | w | rw | |
| A4 _H | CCU6_PISEL2 Reset: 00 _H | Bit Field | | | . (| D | | | IST13HR | |
| | Port Input Select Register 2 | Туре | | | 1 | r | | | r | w |
| FA _H | CCU6_T12L Reset: 00 _H | Bit Field | | | | T12 | CVL | | | |
| | Timer T12 Counter Register Low | Туре | | | | n | vh | | | |
| FB _H | CCU6_T12H Reset: 00 _H | Bit Field | | | | T12 | CVH | | | |
| | Limer 112 Counter Register High | Туре | | | | n | vh | | | |
| FC _H | CCU6_T13L Reset: 00 _H | Bit Field | | | | T13 | CVL | | | |
| | Limer 113 Counter Register Low | Туре | | | | n | vh | | | |
| FD _H | CCU6_T13H Reset: 00 _H | Bit Field | | | | T13 | CVH | | | |
| | Limer 113 Counter Register High | Туре | | | | n | vh | | | |
| FE _H | CCU6_CMPSTATL Reset: 00 _H Compare State Register Low | Bit Field | 0 | CC63 ST | CCPO S2 | CCPO S1 | CCPO S0 | CC62 ST | CC61 ST | CC60 ST |
| | | Туре | r | rh | rh | rh | rh | rh | rh | rh |
| FF _H | CCU6_CMPSTATH Reset: 00 _H Compare State Register High | Bit Field | T13IM | COUT 63PS | COUT 62PS | CC62 PS | COUT 61PS | CC61 PS | COUT 60PS | CC60 PS |
| | | Туре | rwh | rwh | rwh | rwh | rwh | rwh | rwh | rwh |

The SSC SFRs can be accessed in the standard memory area (RMAP = 0).

Table 12 SSC Register Overview

| Addr | Register Name | | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|-----------------|--|------------------------|-----------|----|----|----|----|----|-----|-----|-----|
| RMAP = | RMAP = 0 | | | | | | | | | | |
| A9 _H | A9 _H SSC_PISEL Reset: 00 _H Port Input Select Register | | Bit Field | | | 0 | | | CIS | SIS | MIS |
| | | | Туре | | | r | | rw | rw | rw | |
| AA _H | SSC_CONL | Reset: 00 _H | Bit Field | LB | PO | PH | HB | | BM | | |
| | Control Register Low Programming Mode | | Туре | rw | rw | rw | rw | | r | w | |
| | Operating Mode | | Bit Field | | | 0 | | BC | | | |
| | | | Туре | | | r | | rh | | | |



| AB _H | SSC_CONH Control Register High | Reset: 00 _H | Bit Field | EN | MS | 0 | AREN | BEN | PEN | REN | TEN | |
|-------------------------|-----------------------------------|------------------------|-----------|----|----|---|--------|----------|-----|-----|-----|--|
| | Programming Mode | | Туре | rw | rw | r | rw | rw | rw | rw | rw | |
| | Operating Mode | | Bit Field | EN | MS | 0 | BSY | BE | PE | RE | TE | |
| | | | Туре | rw | rw | r | rh | rwh | rwh | rwh | rwh | |
| ACH | SSC_TBL | Reset: 00 _H | Bit Field | | | | TB_V | ALUE | | | | |
| | Transmitter Buffer Regi | ster Low | Туре | | | | r | N | | | | |
| AD _H | SSC_RBL | Reset: 00 _H | Bit Field | | | | RB_V | ALUE | | | | |
| | Receiver Buffer Registe | er Low | Туре | | rh | | | | | | | |
| AE _H | SSC_BRL | Reset: 00 _H | Bit Field | | | | BR_VAI | UE[7:0] | | | | |
| | Baudrate Timer Reload | Register Low | Туре | | | | r | N | | | | |
| AF _H SSC_BRH | SSC_BRH | Reset: 00 _H | Bit Field | | | | BR_VAL | UE[15:8] |] | | | |
| | Baudrate Timer Reload | Register High | Туре | | | | r | N | | | | |

Table 12 SSC Register Overview

The OCDS SFRs can be accessed in the mapped memory area (RMAP = 1).

Table 13 OCDS Register Overview

| Addr | Register Name | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|-----------------|---|------------------|-------------|-------|-------------|-----------|-------------|-----------|------------|-----------|
| RMAP = | 1 | | | | | | | | | |
| E9 _H | MMCR2 Reset: 0U _H Monitor Mode Control Register 2 | Bit Field | EXBC_ P | EXBC | MBCO N_P | MBCO N | MMEP _P | MMEP | MMOD E | JENA |
| | | Туре | w | rw | w | rwh | w | rwh | rh | rh |
| F1 _H | MMCR Reset: 00 _H Monitor Mode Control Register | Bit Field | MEXIT _P | MEXIT | MSTEP _P | MSTEP | MRAM S_P | MRAM S | TRF | RRF |
| | | Туре | w | rwh | w | rw | w | rwh | rh | rh |
| F2 _H | MMSR Reset: 00 _H Monitor Mode Status Register | Bit Field | MBCA M | MBCIN | EXBF | SWBF | HWB3 F | HWB2 F | HWB1 F | HWB0 F |
| | | Туре | rw | rh | rwh | rwh | rwh | rwh | rwh | rwh |
| F3 _H | MMBPCR Reset: 00 _H BreakPoints Control Register | Bit Field | SWBC | HW | B3C | HW | B2C | HWB1 C | HW | B0C |
| | | Туре | rw | r | w | r | w | rw | r | N |
| F4 _H | MMICR Reset: 00 _H Monitor Mode Interrupt Control Register | Bit Field | DVECT | DRETR | (| D | MMUIE _P | MMUIE | RRIE_ P | RRIE |
| | | Туре | rwh | rwh | | r | w | rw | w | rw |
| F5 _H | MMDR Reset: 00 _H Monitor Mode Data Register | Bit Field | | | | MN | IRR | | | |
| | Receive | Туре | | | | r | h | | | |
| | Transmit | Bit Field | | | | MN | 1TR | | | |
| | | Туре | | | | w | | | | |
| F6 _H | HWBPSR Reset: 00 _H Hardware Breakpoints Select Register | Bit Field | | 0 | BPSEL BPSEL | | SEL | | | |
| | | Туре | | r | | w | | r | w | |
| F7 _H | HWBPDR Reset: 00 _H | Bit Field HWBPxx | | | | | | | | |
| | Hardware Breakpoints Data Register | Туре | | | | r | w | | | |



3.3 Flash Memory

The Flash memory provides an embedded user-programmable non-volatile memory, allowing fast and reliable storage of user code and data. It is operated from a single 2.5 V supply from the Embedded Voltage Regulator (EVR) and does not require additional programming or erasing voltage. The sectorization of the Flash memory allows each sector to be erased independently.

Features

- In-System Programming (ISP) via UART
- In-Application Programming (IAP)
- Error Correction Code (ECC) for dynamic correction of single-bit errors
- Background program and erase operations for CPU load minimization
- Support for aborting erase operation
- Minimum program width¹⁾ of 32-byte for D-Flash and 32-byte for P-Flash
- 1-sector minimum erase width
- 1-byte read access
- Flash is delivered in erased state (read all zeros)
- Operating supply voltage: 2.5 V ± 7.5 %
- Read access time: 3 × t_{CCLK} = 120 ns²⁾
- Program time: 209440 / $f_{SYS} = 2.8 \text{ ms}^{3}$
- Erase time: 8175360 / f_{SYS} = 109 ms³)

P-Flash: 32-byte wordline can only be programmed once, i.e., one gate disturb allowed. D-Flash: 32-byte wordline can be programmed twice, i.e., two gate disturbs allowed.

²⁾ $f_{svs} = 75 \text{ MHz} \pm 7.5\% (f_{CCLK} = 25 \text{ MHz} \pm 7.5\%)$ is the maximum frequency range for Flash read access.

³⁾ $f_{sys} = 75 \text{ MHz} \pm 7.5\%$ is the only frequency range for Flash programming and erasing. f_{sysmin} is used for obtaining the worst case timing.



 Table 14 shows the Flash data retention and endurance targets.

| | Thash Bata Netentio | | | |
|-----------|-------------------------|--|---|---------|
| Retention | Endurance ¹⁾ | | Size | Remarks |
| | | <i>T</i> _A =- 40 to 125 °C | <i>T</i> _A = 125 to 150 ℃ | |

Table 14 Flash Data Retention and Endurance

Program Flash

| - | | | |
|----------|--------------|-------------------------------|-------------------------|
| 20 years | 1,000 cycles | up to 16 Kbytes ²⁾ | for 16-Kbyte Variant |
| 20 years | 1,000 cycles | up to 8 Kbytes ²⁾ | for 8-Kbyte Variant |

Data Flash

| 20 years | 1,000 cycles ³⁾ | 4 Kbytes | 1 Kbytes | |
|----------|------------------------------|-----------|-----------|--|
| 5 years | 10,000 cycles ³⁾ | 1 Kbyte | 256 bytes | |
| 2 years | 70,000 cycles ³⁾ | 512 bytes | 128 bytes | |
| 2 years | 100,000 cycles ³⁾ | 128 bytes | 32 bytes | |

¹⁾ One cycle refers to the programming of all wordlines in a sector and erasing of sector. The Flash endurance data specified in Table 14 is valid only if the following conditions are fulfilled:

- the maximum number of erase cycles per Flash sector must not exceed 100,000 cycles.

- the maximum number of erase cycles per Flash bank must not exceed 300,000 cycles.

- the maximum number of program cycles per Flash bank must not exceed 2,500,000 cycles.

²⁾ If no Flash is used for data, the Program Flash size can be up to the maximum Flash size available in the device variant. Having more Data Flash will mean less Flash is available for Program Flash.

³⁾ For T_A=125 to 150°C, refers to programming of second 8 bytes (bytes 8 to 15) per WL



3.3.1 Flash Bank Sectorization

The SAL-XC866 product family offers four Flash devices with either 8 Kbytes or 16 Kbytes of embedded Flash memory. These Flash memory sizes are made up of two or four 4-Kbyte Flash banks, respectively. Each Flash device consists of Program Flash (P-Flash) bank(s) and a single Data Flash (D-Flash) bank with different sectorization shown in **Figure 10**. Both types can be used for code and data storage. The label "Data" neither implies that the D-Flash is mapped to the data memory region, nor that it can only be used for data storage. It is used to distinguish the different Flash bank sectorizations.



Figure 10 Flash Bank Sectorization

The internal structure of each Flash bank represents a sector architecture for flexible erase capability. The minimum erase width is always a complete sector, and sectors can be erased separately or in parallel. Contrary to standard EPROMs, erased Flash memory cells contain 0s.

The D-Flash bank is divided into more physical sectors for extended erasing and reprogramming capability; even numbers for each sector size are provided to allow greater flexibility and the ability to adapt to a wide range of application requirements.



3.3.2 Flash Programming Width

For the P-Flash banks, a programmed wordline (WL) must be erased before it can be reprogrammed as the Flash cells can only withstand one gate disturb. This means that the entire sector containing the WL must be erased since it is impossible to erase a single WL.

For the D-Flash bank, the same WL can be programmed twice before erasing is required as the Flash cells are able to withstand two gate disturbs. Hence, it is possible to program the same WL, for example, with 16 bytes of data in two times (see Figure 11).



Figure 11 D-Flash Programming

Note: When programming a D-Flash WL the second time, the previously programmed Flash memory cells (whether 0s or 1s) should be reprogrammed with 0s to retain its original contents and to prevent "over-programming".



3.4 Interrupt System

The XC800 Core supports one non-maskable interrupt (NMI) and 14 maskable interrupt requests. In addition to the standard interrupt functions supported by the core, e.g., configurable interrupt priority and interrupt masking, the XC866 interrupt system provides extended interrupt support capabilities such as the mapping of each interrupt vector to several interrupt sources to increase the number of interrupt sources supported, and additional status registers for detecting and determining the interrupt source.

3.4.1 Interrupt Source

Figure 12 to Figure 16 give a general overview of the interrupt sources and illustrates the request and control flags.



Figure 12 Non-Maskable Interrupt Request Sources





Figure 13 Interrupt Request Sources (Part 1)





Figure 14 Interrupt Request Sources (Part 2)





Figure 15 Interrupt Request Sources (Part 3)



SAL-XC866



Figure 16 Interrupt Request Sources (Part 4)



3.4.2 Interrupt Source and Vector

Each interrupt source has an associated interrupt vector address. This vector is accessed to service the corresponding interrupt source request. The interrupt service of each interrupt source can be individually enabled or disabled via an enable bit. The assignment of the SAL-XC866 interrupt sources to the interrupt vector addresses and the corresponding interrupt source enable bits are summarized in Table 15.

| Interrupt Source | Vector Address | Assignment for SAL- XC866 | Enable Bit | SFR |
|---------------------|-------------------|---|------------|--------|
| NMI | 0073 _H | Watchdog Timer NMI | NMIWDT | NMICON |
| | | PLL NMI | NMIPLL | |
| | | Flash NMI | NMIFLASH | |
| | | VDDC Prewarning NMI | NMIVDD | |
| | | VDDP Prewarning NMI | NMIVDDP | |
| | | Flash ECC NMI | NMIECC | |
| XINTR0 | 0003 _H | External Interrupt 0 | EX0 | IEN0 |
| XINTR1 | 000B _H | Timer 0 | ET0 | |
| XINTR2 | 0013 _H | External Interrupt 1 | EX1 | |
| XINTR3 | 001B _H | Timer 1 | ET1 | |
| XINTR4 | 0023 _H | UART | ES | |
| XINTR5 | 002B _H | T2 | ET2 | |
| | | Fractional Divider (Normal Divider Overflow) | | |
| | | LIN | | |

Table 15 Interrupt Vector Addresses



| XINTR6 | 0033 _H | ADC | EADC | IEN1 |
|---------|-------------------|----------------------|--------|------|
| XINTR7 | 003B _H | SSC | ESSC | |
| XINTR8 | 0043 _H | External Interrupt 2 | EX2 | |
| XINTR9 | 004B _H | External Interrupt 3 | EXM | |
| | | External Interrupt 4 | | |
| | | External Interrupt 5 | | |
| | | External Interrupt 6 | * | |
| XINTR10 | 0053 _H | CCU6 INP0 | ECCIP0 | |
| XINTR11 | 005B _H | CCU6 INP1 | ECCIP1 | |
| XINTR12 | 0063 _H | CCU6 INP2 | ECCIP2 | |
| XINTR13 | 006B _H | CCU6 INP3 | ECCIP3 | |

Table 15Interrupt Vector Addresses (cont'd)



3.4.3 Interrupt Priority

Each interrupt source, except for NMI, can be individually programmed to one of the four possible priority levels. The NMI has the highest priority and supersedes all other interrupts. Two pairs of interrupt priority registers (IP and IPH, IP1 and IPH1) are available to program the priority level of each non-NMI interrupt vector.

A low-priority interrupt can be interrupted by a high-priority interrupt, but not by another interrupt of the same or lower priority. Further, an interrupt of the highest priority cannot be interrupted by any other interrupt source.

If two or more requests of different priority levels are received simultaneously, the request of the highest priority is serviced first. If requests of the same priority are received simultaneously, then an internal polling sequence determines which request is serviced first. Thus, within each priority level, there is a second priority structure determined by the polling sequence shown in Table 16.

| Source | Level |
|---|-----------|
| Non-Maskable Interrupt (NMI) | (highest) |
| External Interrupt 0 | 1 |
| Timer 0 Interrupt | 2 |
| External Interrupt 1 | 3 |
| Timer 1 Interrupt | 4 |
| UART Interrupt | 5 |
| Timer 2, Fractional Divider, LIN Interrupts | 6 |
| ADC Interrupt | 7 |
| SSC Interrupt | 8 |
| External Interrupt 2 | 9 |
| External Interrupt [6:3] | 10 |
| CCU6 Interrupt Node Pointer 0 | 11 |
| CCU6 Interrupt Node Pointer 1 | 12 |
| CCU6 Interrupt Node Pointer 2 | 13 |
| CCU6 Interrupt Node Pointer 3 | 14 |

| Table 16 | Priority Structure within Interrupt Level |
|----------|---|
|----------|---|



3.5 Parallel Ports

The SAL-XC866 has 27 port pins organized into four parallel ports, Port 0 (P0) to Port 3 (P3). Each pin has a pair of internal pull-up and pull-down devices that can be individually enabled or disabled. Ports P0, P1 and P3 are bidirectional and can be used as general purpose input/output (GPIO) or to perform alternate input/output functions for the on-chip peripherals. When configured as an output, the open drain mode can be selected. Port P2 is an input-only port, providing general purpose input functions, alternate input functions for the on-chip peripherals, and also analog inputs for the Analog-to-Digital Converter (ADC).

Bidirectional Port Features:

- Configurable pin direction
- · Configurable pull-up/pull-down devices
- · Configurable open drain mode
- Transfer of data through digital inputs and outputs (general purpose I/O)
- · Alternate input/output for on-chip peripherals

Input Port Features:

- Configurable input driver
- Configurable pull-up/pull-down devices
- Receive of data through digital input (general purpose input)
- · Alternate input for on-chip peripherals
- Analog input for ADC module





Figure 17 General Structure of Bidirectional Port







Figure 18 General Structure of Input Port



3.6 Power Supply System with Embedded Voltage Regulator

The SAL-XC866 microcontroller requires two different levels of power supply:

- 3.3 V or 5.0 V for the Embedded Voltage Regulator (EVR) and Ports
- 2.5 V for the core, memory, on-chip oscillator, and peripherals

Figure 19 shows the SAL-XC866 power supply system. A power supply of 3.3 V or 5.0 V must be provided from the external power supply pin. The 2.5 V power supply for the logic is generated by the EVR. The EVR helps to reduce the power consumption of the whole chip and the complexity of the application board design.

The EVR consists of a main voltage regulator and a low power voltage regulator. In active mode, both voltage regulators are enabled. In power-down mode, the main voltage regulator is switched off, while the low power voltage regulator continues to function and provide power supply to the system with low power consumption.



Figure 19 SAL-XC866 Power Supply System

EVR Features:

- Input voltage (V_{DDP}): 3.3 V/5.0 V
- Output voltage (V_{DDC}): 2.5 V ± 7.5%
- · Low power voltage regulator provided in power-down mode
- V_{DDC} and V_{DDP} prewarning detection
- V_{DDC} brownout detection



3.7 Reset Control

The SAL-XC866 has five types of reset: power-on reset, hardware reset, watchdog timer reset, power-down wake-up reset, and brownout reset.

When the SAL-XC866 is first powered up, the status of certain pins (see **Table 18**) must be defined to ensure proper start operation of the device. At the end of a reset sequence, the sampled values are latched to select the desired boot option, which cannot be modified until the next power-on reset or hardware reset. This guarantees stable conditions during the normal operation of the device.

In order to power up the system properly, the external reset pin $\overrightarrow{\text{RESET}}$ must be asserted until V_{DDC} reaches 0.9* V_{DDC} . The delay of external reset can be realized by an external capacitor at $\overrightarrow{\text{RESET}}$ pin. This capacitor value must be selected so that V_{RESET} reaches 0.4 V, but not before V_{DDC} reaches 0.9* V_{DDC} .

A typical application example is shown in Figure 20. V_{DDP} capacitor value is 300 nF. V_{DDC} capacitor value is 220 nF. The capacitor connected to RESET pin is 100 nF.

Typically, the time taken for V_{DDC} to reach 0.9^*V_{DDC} is less than 50 µs once V_{DDP} reaches 2.3V. Hence, based on the condition that 10% to 90% V_{DDP} (slew rate) is less than 500 µs, the RESET pin should be held low for 500 µs typically. See Figure 21.









Figure 21 V_{DDP}, V_{DDC} and V_{RESET} during Power-on Reset

The second type of reset in SAL-XC866 is the hardware reset. This reset function can be used during normal operation or when the chip is in power-down mode. A reset input pin RESET is provided for the hardware reset. To ensure the recognition of the hardware reset, pin RESET must be held low for at least 100 ns.

The Watchdog Timer (WDT) module is also capable of resetting the device if it detects a malfunction in the system.

Another type of reset that needs to be detected is a reset while the device is in power-down mode (wake-up reset). While the contents of the static RAM are undefined after a power-on reset, they are well defined after a wake-up reset from power-down mode.



3.7.1 Module Reset Behavior

Table 17 shows how the functions of the SAL-XC866 are affected by the various reset types. A "∎" means that this function is reset to its default state.

| Module/ Function | Wake-Up Reset | Watchdog Reset | Hardware Reset | Power-On Reset | Brownout Reset |
|-----------------------|--------------------------------------|------------------------|------------------------|---------------------------|---------------------------|
| CPU Core | | | | | |
| Peripherals | | | | | |
| On-Chip Static RAM | Not affected, reliable | Not affected, reliable | Not affected, reliable | Affected, un- reliable | Affected, un- reliable |
| Oscillator, PLL | | Not affected | | | |
| Port Pins | | | | | |
| EVR | The voltage regulator is switched on | Not affected | | | |
| FLASH | | | | | |
| NMI | Disabled | Disabled | | | |

Table 17 Effect of Reset on Device Functions

3.7.2 Booting Scheme

When the SAL-XC866 is reset, it must identify the type of configuration with which to start the different modes once the reset sequence is complete. Thus, boot configuration information that is required for activation of special modes and conditions needs to be applied by the external world through input pins. After power-on reset or hardware reset, the pins MBC, TMS and P0.0 collectively select the different boot options. Table 18 shows the available boot options in the SAL-XC866.

| МВС | TMS | P0.0 | Type of Mode | PC Start Value |
|-----|-----|------|--|-------------------|
| 1 | 0 | х | User Mode; on-chip OSC/PLL non-bypassed | 0000 _H |
| 0 | 0 | х | BSL Mode; on-chip OSC/PLL non-bypassed | 0000 _H |
| 0 | 1 | 0 | OCDS Mode ¹⁾ ; on-chip OSC/PLL non- bypassed | 0000 _H |
| 1 | 1 | 0 | Standalone User (JTAG) Mode ²⁾ ; on-chip OSC/PLL non-bypassed (normal) | 0000 _H |

Table 18 SAL-XC866 Boot Selection

¹⁾ The OCDS mode is not accessible if Flash is protected.

²⁾ Normal user mode with standard JTAG (TCK,TDI,TDO) pins for hot-attach purpose.



3.8 Clock Generation Unit

The Clock Generation Unit (CGU) allows great flexibility in the clock generation for the SAL-XC866. The power consumption is indirectly proportional to the frequency, whereas the performance of the microcontroller is directly proportional to the frequency. During user program execution, the frequency can be programmed for an optimal ratio between performance and power consumption. Therefore the power consumption can be adapted to the actual application state.

Features:

- Phase-Locked Loop (PLL) for multiplying clock source by different factors
- PLL Base Mode
- Prescaler Mode
- PLL Mode
- Power-down mode support

The CGU consists of an oscillator circuit and a PLL.In the SAL-XC866, the oscillator can be from either of these two sources: the on-chip oscillator (10 MHz) or the external oscillator (4 MHz to 12 MHz). The term "oscillator" is used to refer to both on-chip oscillator and external oscillator, unless otherwise stated. After the reset, the on-chip oscillator will be used by default. The external oscillator can be selected via software. In addition, the PLL provides a fail-safe logic to perform oscillator run and loss-of-lock detection. This allows emergency routines to be executed for system recovery or to perform system shut down.



Figure 22 CGU Block Diagram



The clock system provides three ways to generate the system clock:

PLL Base Mode

The system clock is derived from the VCO base (free running) frequency clock divided by the K factor.

$$f_{SYS} = f_{VCObase} \times \frac{1}{K}$$

Prescaler Mode (VCO Bypass Operation)

In VCO bypass operation, the system clock is derived from the oscillator clock, divided by the P and K factors.

$$f_{SYS} = f_{OSC} \times \frac{1}{P \times K}$$

PLL Mode

The system clock is derived from the oscillator clock, multiplied by the N factor, and divided by the P and K factors. Both VCO bypass and PLL bypass must be inactive for this PLL mode. The PLL mode is used during normal system operation.

$$f_{SYS} = f_{OSC} \times \frac{N}{P \times K}$$

 Table 19 shows the settings of bits OSCDISC and VCOBYP for different clock mode selection.

| OSCDISC | VCOBYP | Clock Working Modes |
|---------|--------|---------------------|
| 0 | 0 | PLL Mode |
| 0 | 1 | Prescaler Mode |
| 1 | 0 | PLL Base Mode |
| 1 | 1 | PLL Base Mode |

| Table 19 | Clock Mode | Selection |
|----------|------------|-----------|
|----------|------------|-----------|

Note: When oscillator clock is disconnected from PLL, the clock mode is PLL Base mode regardless of the setting of VCOBYP bit.

System Frequency Selection

For the SAL-XC866, the values of P and K are fixed to "1" and "2", respectively. In order to obtain the required system frequency, f_{sys} , the value of N can be selected by bit NDIV for different oscillator inputs. Table 20 provides examples on how $f_{sys} = 75$ MHz can be obtained for the different oscillator sources.



| Table 20 System frequency (f _{sys} = 75 MHZ) | | | | | | |
|---|--|------------------|----|---|---|------------------|
| Oscillator | | f _{osc} | Ν | Ρ | к | f _{sys} |
| On-chip | | 10 MHz | 15 | 1 | 2 | 75 MHz |
| External | | 10 MHz | 15 | 1 | 2 | 75 MHz |
| | | 5 MHz | 30 | 1 | 2 | 75 MHz |

Table 21 shows the VCO range for the SAL-XC866.

| Table | 21 | VCO | Range |
|-------|----|-----|-------|
| | | | |

| f _{VCOmin} | f _{VCOmax} | f _{VCOFREEmin} | f _{VCOFREEmax} | Unit |
|---------------------|---------------------|-------------------------|-------------------------|------|
| 150 | 200 | 20 | 80 | MHz |
| 100 | 150 | 10 | 80 | MHz |

3.8.1 Recommended External Oscillator Circuits

The oscillator circuit, a Pierce oscillator, is designed to work with both, an external crystal oscillator or an external stable clock source. It basically consists of an inverting amplifier and a feedback element with XTAL1 as input, and XTAL2 as output.

When using a crystal, a proper external oscillator circuitry must be connected to both pins, XTAL1 and XTAL2. The crystal frequency can be within the range of 4 MHz to 12 MHz. Additionally, it is necessary to have two load capacitances C_{x1} and C_{x2} , and depending on the crystal type, a series resistor R_{χ_2} , to limit the current. A test resistor $R_{\rm O}$ may be temporarily inserted to measure the oscillation allowance (negative resistance) of the oscillator circuitry. R_Q values are typically specified by the crystal vendor. The C_{X1} and C_{X2} values shown in Figure 23 can be used as starting points for the negative resistance evaluation and for non-productive systems. The exact values and related operating range are dependent on the crystal frequency and have to be determined and optimized together with the crystal vendor using the negative resistance method. Oscillation measurement with the final target system is strongly recommended to verify the input amplitude at XTAL1 and to determine the actual oscillation allowance (margin negative resistance) for the oscillator-crystal system.

When using an external clock signal, the signal must be connected to XTAL1. XTAL2 is left open (unconnected).

The oscillator can also be used in combination with a ceramic resonator. The final circuitry must also be verified by the resonator vendor.

Figure 23 shows the recommended external oscillator circuitries for both operating modes, external crystal mode and external input clock mode.





Figure 23 External Oscillator Circuitries

Note: For crystal operation, it is strongly recommended to measure the negative resistance in the final target system (layout) to determine the optimum parameters for the oscillator operation. Please refer to the minimum and maximum values of the negative resistance specified by the crystal supplier.



3.8.2 Clock Management

The CGU generates all clock signals required within the microcontroller from a single clock, f_{sys} . During normal system operation, the typical frequencies of the different modules are as follow:

- CPU clock: CCLK, SCLK = 25 MHz
- CCU6 clock: FCLK = 25 MHz
- Other peripherals: PCLK = 25 MHz
- Flash Interface clock: CCLK3 = 75 MHz and CCLK = 25 MHz

In addition, different clock frequency can output to pin CLKOUT(P0.0). The clock output frequency can further be divided by 2 using toggle latch (bit TLEN is set to 1), the resulting output frequency has 50% duty cycle. **Figure 24** shows the clock distribution of the SAL-XC866.



Figure 24 Clock Generation from f_{svs}



For power saving purposes, the clocks may be disabled or slowed down according to **Table 22**.

Table 22System frequency (f_{svs} = 75 MHz)

| Power Saving Mode | Action |
|-------------------|---|
| Idle | Clock to the CPU is disabled. |
| Slow-down | Clocks to the CPU and all the peripherals, including CCU6, are divided by a common programmable factor defined by bit field CMCON.CLKREL. |
| Power-down | Oscillator and PLL are switched off. |



3.9 Power Saving Modes

The power saving modes of the SAL-XC866 provide flexible power consumption through a combination of techniques, including:

- Stopping the CPU clock
- Stopping the clocks of individual system components
- Reducing clock speed of some peripheral components
- · Power-down of the entire system with fast restart capability

After a reset, the active mode (normal operating mode) is selected by default (see **Figure 25**) and the system runs in the main system clock frequency. From active mode, different power saving modes can be selected by software. They are:

- Idle mode
- Slow-down mode
- Power-down mode



Figure 25 Transition between Power Saving Modes



3.10 Watchdog Timer

The Watchdog Timer (WDT) provides a highly reliable and secure way to detect and recover from software or hardware failures. The WDT is reset at a regular interval that is predefined by the user. The CPU must service the WDT within this interval to prevent the WDT from causing an SAL-XC866 system reset. Hence, routine service of the WDT confirms that the system is functioning properly. This ensures that an accidental malfunction of the SAL-XC866 will be aborted in a user-specified time period. In debug mode, the WDT is suspended and stops counting. Therefore, there is no need to refresh the WDT during debugging.

Features:

- 16-bit Watchdog Timer
- Programmable reload value for upper 8 bits of timer
- · Programmable window boundary
- Selectable input frequency of f_{PCLK}/2 or f_{PCLK}/128
- Time-out detection with NMI generation and reset prewarning activation (after which a system reset will be performed)

The WDT is a 16-bit timer incremented by a count rate of $f_{PCLK}/2$ or $f_{PCLK}/128$. This 16-bit timer is realized as two concatenated 8-bit timers. The upper 8 bits of the WDT can be preset to a user-programmable value via a watchdog service access in order to modify the watchdog expire time period. The lower 8 bits are reset on each service access. Figure 26 shows the block diagram of the WDT unit.







If the WDT is not serviced before the timer overflow, a system malfunction is assumed. As a result, the WDT NMI is triggered (assert WDTTO) and the reset prewarning is entered. The prewarning period lasts for $30_{\rm H}$ count, after which the system is reset (assert WDTRST).

The WDT has a "programmable window boundary" which disallows any refresh during the WDT's count-up. A refresh during this window boundary constitutes an invalid access to the WDT, causing the reset prewarning to be entered but without triggering the WDT NMI. The system will still be reset after the prewarning period is over. The window boundary is from $0000_{\rm H}$ to the value obtained from the concatenation of WDTWINB and $00_{\rm H}$.

After being serviced, the WDT continues counting up from the value (<WDTREL> $* 2^8$). The time period for an overflow of the WDT is programmable in two ways:

- the input frequency to the WDT can be selected to be either f_{PCLK}/2 or f_{PCLK}/128
- the reload value WDTREL for the high byte of WDT can be programmed in register WDTREL

The period, P_{WDT} , between servicing the WDT and the next overflow can be determined by the following formula:

$$P_{WDT} = \frac{2^{(1+WDTIN \times 6)} \times (2^{16} - WDTREL \times 2^8)}{f_{PCLK}}$$

If the Window-Boundary Refresh feature of the WDT is enabled, the period P_{WDT} between servicing the WDT and the next overflow is shortened if WDTWINB is greater than WDTREL, see Figure 27. This period can be calculated using the same formula by replacing WDTREL with WDTWINB. For this feature to be useful, WDTWINB should not be smaller than WDTREL.



Figure 27 WDT Timing Diagram



 Table 23 lists the possible watchdog time range that can be achieved for different module clock frequencies. Some numbers are rounded to 3 significant digits.

| Reload value in WDTREL | Prescaler for f _{PCLK} | | | |
|---------------------------|---------------------------------|-----------------|--|--|
| | 2 (WDTIN = 0) | 128 (WDTIN = 1) | | |
| | 25 MHz | 25 MHz | | |
| FF _H | 20.5 μs | 1.31 ms | | |
| 7F _H | 2.64 ms | 169 ms | | |
| 00 _H | 5.24 ms | 336 ms | | |

Table 23 Watchdog Time Ranges



3.11 Universal Asynchronous Receiver/Transmitter

The Universal Asynchronous Receiver/Transmitter (UART) provides a full-duplex asynchronous receiver/transmitter, i.e., it can transmit and receive simultaneously. It is also receive-buffered, i.e., it can commence reception of a second byte before a previously received byte has been read from the receive register. However, if the first byte still has not been read by the time reception of the second byte is complete, one of the bytes will be lost.

Features:

- Full-duplex asynchronous modes
 - 8-bit or 9-bit data frames, LSB first
 - fixed or variable baud rate
- Receive buffered
- Multiprocessor communication
- Interrupt generation on the completion of a data transmission or reception

The UART can operate in four asynchronous modes as shown in **Table 24**. Data is transmitted on TXD and received on RXD.

| Table 24 UA | RT Modes |
|-------------|----------|
|-------------|----------|

| Operating Mode | Baud Rate |
|------------------------------|--|
| Mode 0: 8-bit shift register | f _{PCLK} /2 |
| Mode 1: 8-bit shift UART | Variable |
| Mode 2: 9-bit shift UART | f _{PCLK} /32 or f _{PCLK} /64 |
| Mode 3: 9-bit shift UART | Variable |

There are several ways to generate the baud rate clock for the serial port, depending on the mode in which it is operating. In mode 0, the baud rate for the transfer is fixed at $f_{PCLK}/2$. In mode 2, the baud rate is generated internally based on the UART input clock and can be configured to either $f_{PCLK}/32$ or $f_{PCLK}/64$. The variable baud rate is set by either the underflow rate on the dedicated baud-rate generator, or by the overflow rate on Timer 1.



3.11.1 Baud-Rate Generator

The baud-rate generator is based on a programmable 8-bit reload value, and includes divider stages (i.e., prescaler and fractional divider) for generating a wide range of baud rates based on its input clock f_{PCLK}, see Figure 28.



Figure 28 Baud-rate Generator Circuitry

The baud rate timer is a count-down timer and is clocked by either the output of the fractional divider (f_{MOD}) if the fractional divider is enabled (FDCON.FDEN = 1), or the output of the prescaler (f_{DIV}) if the fractional divider is disabled (FDEN = 0). For baud rate generation, the fractional divider must be configured to fractional divider mode (FDCON.FDM = 0). This allows the baud rate control run bit BCON.R to be used to start or stop the baud rate timer. At each timer underflow, the timer is reloaded with the 8-bit reload value in register BG and one clock pulse is generated for the serial channel.

Enabling the fractional divider in normal divider mode (FDEN = 1 and FDM = 1) stops the baud rate timer and nullifies the effect of bit BCON.R. See Section 3.12.

The baud rate (f_{BR}) value is dependent on the following parameters:

- Input clock f_{PCLK}
- Prescaling factor (2^{BRPRE}) defined by bit field BRPRE in register BCON
- Fractional divider (STEP/256) defined by register FDSTEP (to be considered only if fractional divider is enabled and operating in fractional divider mode)


8-bit reload value (BR_VALUE) for the baud rate timer defined by register BG
 The following formulas calculate the final baud rate without and with the fractional divider respectively:

baud rate =
$$\frac{f_{PCLK}}{16 \times 2^{BRPRE} \times (BR_VALUE + 1)}$$
 where $2^{BRPRE} \times (BR_VALUE + 1) > 1$

baud rate =
$$\frac{f_{PCLK}}{16 \times 2^{BRPRE} \times (BR VALUE + 1)} \times \frac{STEP}{256}$$

The maximum baud rate that can be generated is limited to $f_{PCLK}/32$. Hence, for a module clock of 25 MHz, the maximum achievable baud rate is 0.78 MBaud.

Standard LIN protocol can support a maximum baud rate of 20kHz, the baud rate accuracy is not critical and the fractional divider can be disabled. Only the prescaler is used for auto baud rate calculation. For LIN fast mode, which supports the baud rate of 20kHz to 115.2kHz, the higher baud rates require the use of the fractional divider for greater accuracy.

Table 25 lists the various commonly used baud rates with their corresponding parameter settings and deviation errors. The fractional divider is disabled and a module clock of 25 MHz is used.

| Baud rate | Prescaling Factor (2 ^{BRPRE}) | Reload Value (BR_VALUE + 1) | Deviation Error | |
|------------|--|--------------------------------|-----------------|--|
| 19.2 kBaud | 1 (BRPRE=000 _B) | 81 (51 _H) | -0.47 % | |
| 9600 Baud | 1 (BRPRE=000 _B) | 162 (A2 _H) | -0.47 % | |
| 4800 Baud | 2 (BRPRE=001 _B) | 162 (A2 _H) | -0.47 % | |
| 2400 Baud | 4 (BRPRE=010 _B) | 162 (A2 _H) | -0.47 % | |

| Table 25 | Typical Baud rates for UART with Fractional Divider disabled |
|----------|--|
| | |

The fractional divider allows baud rates of higher accuracy (lower deviation error) to be generated. **Table 26** lists the resulting deviation errors from generating a baud rate of 115.2 kHz, using different module clock frequencies. The fractional divider is enabled (fractional divider mode) and the corresponding parameter settings are shown.



Table 26 Deviation Error for UART with Fractional Divider enabled

| f _{PCLK} | Prescaling Factor (2 ^{BRPRE}) | Reload Value (BR_VALUE + 1) | STEP | Deviation Error |
|-------------------|--|--------------------------------|------------------------|--------------------|
| 25 MHz | 1 | 10 (A _H) | 189 (BD _H) | +0.14 % |
| 12.5 MHz | 1 | 6 (6 _H) | 226 (E2 _H) | -0.22 % |
| 6.25 MHz | 1 | 3 (3 _H) | 226 (E2 _H) | -0.22 % |





3.11.2 Baud Rate Generation using Timer 1

In UART modes 1 and 3, Timer 1 can be used for generating the variable baud rates. In theory, this timer could be used in any of its modes. But in practice, it should be set into auto-reload mode (Timer 1 mode 2), with its high byte set to the appropriate value for the required baud rate. The baud rate is determined by the Timer 1 overflow rate and the value of SMOD as follows:

[3.1]

Mode 1, 3 baud rate= $\frac{2^{\text{SMOD}} \times f_{\text{PCLK}}}{32 \times 2 \times (256 - \text{TH1})}$

3.12 Normal Divider Mode (8-bit Auto-reload Timer)

Setting bit FDM in register FDCON to 1 configures the fractional divider to normal divider mode, while at the same time disables baud rate generation (see **Figure 28**). Once the fractional divider is enabled (FDEN = 1), it functions as an 8-bit auto-reload timer (with no relation to baud rate generation) and counts up from the reload value with each input clock pulse. Bit field RESULT in register FDRES represents the timer value, while bit field STEP in register FDSTEP defines the reload value. At each timer overflow, an overflow flag (FDCON.NDOV) will be set and an interrupt request generated. This gives an output clock f_{MOD} that is 1/n of the input clock f_{DIV} , where n is defined by 256 - STEP.

The output frequency in normal divider mode is derived as follows:

 $f_{MOD} = f_{DIV} \times \frac{1}{256 - STEP}$ [3.2]



3.13 LIN Protocol

The UART can be used to support the Local Interconnect Network (LIN) protocol for both master and slave operations. The LIN baud rate detection feature provides the capability to detect the baud rate within LIN protocol using Timer 2. This allows the UART to be synchronized to the LIN baud rate for data transmission and reception.

LIN is a holistic communication concept for local interconnected networks in vehicles. The communication is based on the SCI (UART) data format, a single-master/multipleslave concept, a clock synchronization for nodes without stabilized time base. An attractive feature of LIN is self-synchronization of the slave nodes without a crystal or ceramic resonator, which significantly reduces the cost of hardware platform. Hence, the baud rate must be calculated and returned with every message frame.

The structure of a LIN frame is shown in Figure 29. The frame consists of the:

- header, which comprises a Break (13-bit time low), Synch Byte (55_H), and ID field
- response time
- data bytes (according to UART protocol)
- checksum



Figure 29 Structure of LIN Frame

3.13.1 LIN Header Transmission

LIN header transmission is only applicable in master mode. In the LIN communication, a master task decides when and which frame is to be transferred on the bus. It also identifies a slave task to provide the data transported by each frame. The information needed for the handshaking between the master and slave tasks is provided by the master task through the header portion of the frame.

The header consists of a break and synch pattern followed by an identifier. Among these three fields, only the break pattern cannot be transmitted as a normal 8-bit UART data.



The break must contain a dominant value of 13 bits or more to ensure proper synchronization of slave nodes.

In the LIN communication, a slave task is required to be synchronized at the beginning of the protected identifier field of frame. For this purpose, every frame starts with a sequence consisting of a break field followed by a synch byte field. This sequence is unique and provides enough information for any slave task to detect the beginning of a new frame and be synchronized at the start of the identifier field.

Upon entering LIN communication, a connection is established and the transfer speed (baud rate) of the serial communication partner (host) is automatically synchronized in the following steps:

STEP 1: Initialize interface for reception and timer for baud rate measurement

STEP 2: Wait for an incoming LIN frame from host

STEP 3: Synchronize the baud rate to the host

STEP 4: Enter for Master Request Frame or for Slave Response Frame

Note: Re-synchronization and setup of baud rate are always done for **every** Master Request Header or Slave Response Header LIN frame.



3.14 High-Speed Synchronous Serial Interface

The High-Speed Synchronous Serial Interface (SSC) supports full-duplex and half-duplex synchronous communication. The serial clock signal can be generated by the SSC internally (master mode), using its own 16-bit baud-rate generator, or can be received from an external master (slave mode). Data width, shift direction, clock polarity and phase are programmable. This allows communication with SPI-compatible devices or devices using other synchronous serial interfaces.

Features:

- Master and slave mode operation
 - Full-duplex or half-duplex operation
- Transmit and receive buffered
- Flexible data format
 - Programmable number of data bits: 2 to 8 bits
 - Programmable shift direction: LSB or MSB shift first
 - Programmable clock polarity: idle low or high state for the shift clock
 - Programmable clock/data phase: data shift with leading or trailing edge of the shift clock
- Variable baud rate
- Compatible with Serial Peripheral Interface (SPI)
- Interrupt generation
 - On a transmitter empty condition
 - On a receiver full condition
 - On an error condition (receive, phase, baud rate, transmit error)



Data is transmitted or received on lines TXD and RXD, which are normally connected to the pins MTSR (Master Transmit/Slave Receive) and MRST (Master Receive/Slave Transmit). The clock signal is output via line MS_CLK (Master Serial Shift Clock) or input via line SS_CLK (Slave Serial Shift Clock). Both lines are normally connected to the pin SCLK. Transmission and reception of data are double-buffered.

Figure 30 shows the block diagram of the SSC.



Figure 30 SSC Block Diagram



3.15 Timer 0 and Timer 1

Timers 0 and 1 are count-up timers which are incremented every machine cycle, or in terms of the input clock, every 2 PCLK cycles. They are fully compatible and can be configured in four different operating modes for use in a variety of applications, see **Table 27**. In modes 0, 1 and 2, the two timers operate independently, but in mode 3, their functions are specialized.

| Mode | Operation |
|------|--|
| 0 | 13-bit timer The timer is essentially an 8-bit counter with a divide-by-32 prescaler. This mode is included solely for compatibility with Intel 8048 devices. |
| 1 | 16-bit timer The timer registers, TLx and THx, are concatenated to form a 16-bit counter. |
| 2 | 8-bit timer with auto-reload The timer register TLx is reloaded with a user-defined 8-bit value in THx upon overflow. |
| 3 | Timer 0 operates as two 8-bit timers The timer registers, TL0 and TH0, operate as two separate 8-bit counters. Timer 1 is halted and retains its count even if enabled. |

Table 27 Timer 0 and Timer 1 Modes



3.16 Timer 2

Timer 2 is a 16-bit general purpose timer (THL2) that has two modes of operation, a 16-bit auto-reload mode and a 16-bit one channel capture mode. If the prescalar is disabled, Timer 2 counts with an input clock of PCLK/12. Timer 2 continues counting as long as it is enabled.

| Table 28 | Timer 2 Modes | | | | | | |
|--------------------|--|--|--|--|--|--|--|
| Mode | Description | | | | | | |
| Auto-reload | Up/Down Count Disabled Count up only Start counting from 16-bit reload value, overflow at FFFF_H Reload event configurable for trigger by overflow condition only, or by negative/positive edge at input pin T2EX as well Programmble reload value in register RC2 Interrupt is generated with reload event | | | | | | |
| | Up/Down Count Enabled Count up or down, direction determined by level at input pin T2EX No interrupt is generated Count up Start counting from 16-bit reload value, overflow at FFF_H Reload event triggered by overflow condition Programmble reload value in register RC2 Count down Start counting from FFF_H, underflow at value defined in register RC2 Reload event triggered by underflow condition RC2 Reload event triggered by underflow condition Reload value fixed at FFF_H | | | | | | |
| Channel capture | Count up only Start counting from 0000_H, overflow at FFFF_H Reload event triggered by overflow condition Reload value fixed at 0000_H Capture event triggered by falling/rising edge at pin T2EX Captured timer value stored in register RC2 Interrupt is generated with reload or capture event | | | | | | |



3.17 Capture/Compare Unit 6

The Capture/Compare Unit 6 (CCU6) provides two independent timers (T12, T13), which can be used for Pulse Width Modulation (PWM) generation, especially for AC-motor control. The CCU6 also supports special control modes for block commutation and multi-phase machines.

The timer T12 can function in capture and/or compare mode for its three channels. The timer T13 can work in compare mode only.

The multi-channel control unit generates output patterns, which can be modulated by T12 and/or T13. The modulation sources can be selected and combined for the signal modulation.

Timer T12 Features:

- Three capture/compare channels, each channel can be used either as a capture or as a compare channel
- Supports generation of a three-phase PWM (six outputs, individual signals for highside and lowside switches)
- 16-bit resolution, maximum count frequency = peripheral clock frequency
- Dead-time control for each channel to avoid short-circuits in the power stage
- Concurrent update of the required T12/13 registers
- · Generation of center-aligned and edge-aligned PWM
- Supports single-shot mode
- · Supports many interrupt request sources
- · Hysteresis-like control mode

Timer T13 Features:

- One independent compare channel with one output
- 16-bit resolution, maximum count frequency = peripheral clock frequency
- Can be synchronized to T12
- Interrupt generation at period-match and compare-match
- Supports single-shot mode

Additional Features:

- Implements block commutation for Brushless DC-drives
- Position detection via Hall-sensor pattern
- Automatic rotational speed measurement for block commutation
- Integrated error handling
- Fast emergency stop without CPU load via external signal (CTRAP)
- Control modes for multi-channel AC-drives
- Output levels can be selected and adapted to the power stage





The block diagram of the CCU6 module is shown in Figure 31.

Figure 31 CCU6 Block Diagram



3.18 Analog-to-Digital Converter

The SAL-XC866 includes a high-performance 10-bit Analog-to-Digital Converter (ADC) with eight multiplexed analog input channels. The ADC uses a successive approximation technique to convert the analog voltage levels from up to eight different sources. The analog input channels of the ADC are available at Port 2.

Features:

- Successive approximation
- 8-bit or 10-bit resolution
- Eight analog channels
- · Four independent result registers
- Result data protection for slow CPU access (wait-for-read mode)
- Single conversion mode
- Autoscan functionality
- · Limit checking for conversion results
- Data reduction filter (accumulation of up to 2 conversion results)
- Two independent conversion request sources with programmable priority
- Selectable conversion request trigger
- · Flexible interrupt generation with configurable service nodes
- Programmable sample time
- · Programmable clock divider
- · Cancel/restart feature for running conversions
- Integrated sample and hold circuitry
- Compensation of offset errors
- · Low power modes



3.18.1 ADC Clocking Scheme

A common module clock ${\rm f}_{\rm ADC}$ generates the various clock signals used by the analog and digital parts of the ADC module:

- f_{ADCA} is input clock for the analog part.
- f_{ADCI} is internal clock for the analog part (defines the time base for conversion length and the sample time). This clock is generated internally in the analog part, based on the input clock f_{ADCA} to generate a correct duty cycle for the analog components.
- f_{ADCD} is input clock for the digital part.

The internal clock for the analog part f_{ADCI} is limited to a maximum frequency of 10 MHz. Therefore, the ADC clock prescaler must be programmed to a value that ensures f_{ADCI} does not exceed 10 MHz. The prescaler ratio is selected by bit field CTC in register GLOBCTR. A prescaling ratio of 32 can be selected when the maximum performance of the ADC is not required.



Figure 32 ADC Clocking Scheme



For module clock f_{ADC} = 25 MHz, the analog clock f_{ADCI} frequency can be selected as shown in **Table 29**.

| Module Clock f _{ADC} | СТС | Prescaling Ratio | Analog Clock f _{ADCI} | |
|-------------------------------|---------------------------|------------------|--------------------------------|--|
| 25 MHz | 00 _B | ÷ 2 | 12.5 MHz (N.A) | |
| | 01 _B | ÷ 3 | 8.3 MHz | |
| | 10 _B | ÷ 4 | 6.3 MHz | |
| | 11 _B (default) | ÷ 32 | 781.3 kHz | |

Table 29fFrequency Selection

As f_{ADCI} cannot exceed 10 MHz, bit field CTC should not be set to 00_B when f_{ADC} is 25 MHz. During slow-down mode where f_{ADC} may be reduced to 12.5 MHz, 6.25 MHz etc., CTC can be set to 00_B as long as the divided analog clock f_{ADCI} does not exceed 10 MHz. However, it is important to note that the conversion error could increase due to loss of charges on the capacitors, if f_{ADC} becomes too low during slow-down mode.

3.18.2 ADC Conversion Sequence

The analog-to-digital conversion procedure consists of the following phases:

- Synchronization phase (t_{SYN})
- Sample phase (t_S)
- Conversion phase
- Write result phase (t_{WR})



Figure 33 ADC Conversion Timing



3.19 On-Chip Debug Support

The On-Chip Debug Support (OCDS) provides the basic functionality required for the software development and debugging of XC800-based systems.

The OCDS design is based on these principles:

- use the built-in debug functionality of the XC800 Core
- add a minimum of hardware overhead
- · provide support for most of the operations by a Monitor Program
- use standard interfaces to communicate with the Host (a Debugger)

Features:

- Set breakpoints on instruction address and within a specified address range
- Set breakpoints on internal RAM address
- Support unlimited software breakpoints in Flash/RAM code region
- Process external breaks
- Step through the program code

The OCDS functional blocks are shown in **Figure 34**. The Monitor Mode Control (MMC) block at the center of OCDS system brings together control signals and supports the overall functionality. The MMC communicates with the XC800 Core, primarily via the Debug Interface, and also receives reset and clock signals. After processing memory address and control signals from the core, the MMC provides proper access to the dedicated extra-memories: a Monitor ROM (holding the code) and a Monitor RAM (for work-data and Monitor-stack). The OCDS system is accessed through the JTAG¹, which is an interface dedicated exclusively for testing and debugging activities and is not normally used in an application. The dedicated MBC pin is used for external configuration and debugging control.

Note: All the debug functionality described here can normally be used only after SAL-XC866 has been started in OCDS mode.

¹⁾ The pins of the JTAG port can be assigned to either Port 0 (primary) or Ports 1 and 2 (secondary). User must set the JTAG pins (TCK and TDI) as input during connection with the OCDS system.







3.19.1 JTAG ID Register

This is a read-only register located inside the JTAG module, and is used to recognize the device(s) connected to the JTAG interface. Its content is shifted out when INSTRUCTION register contains the IDCODE command (opcode 04_H), and the same is also true immediately after reset.

The JTAG ID register contents for the SAL-XC866 devices are given in Table 30.

| Device Type | Device Name | JTAG ID |
|-------------|-----------------|------------------------|
| Flash | SAL-XC866L-4FRA | 1010 0083 _H |
| | SAL-XC866L-2FRA | 1010 2083 _H |



3.20 Identification Register

The SAL-XC866 identity register is located at Page 1 of address B3_H.

ID

Identity Register

Reset Value: 0000 0010_B

| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|--------|---|---|---|---|-------|---|---|
| PRODID | | | | | VERID | | |
| 1 | | 1 | | 1 | | | |
| r | | | | | r | | |

| Field | Bits | Туре | Description |
|--------|-------|------|----------------------------------|
| VERID | [2:0] | r | Version ID 010 _B |
| PRODID | [7:3] | r | Product ID 00000 _B |



4 Electrical Parameters

Chapter 4 provides the characteristics of the electrical parameters which are implementation-specific for the SAL-XC866.

4.1 General Parameters

The general parameters are described here to aid the users in interpreting the parameters mainly in **Section 4.2** and **Section 4.3**.

4.1.1 Parameter Interpretation

The parameters listed in this section represent partly the characteristics of the SAL-XC866 and partly its requirements on the system. To aid interpreting the parameters easily when evaluating them for a design, they are indicated by the abbreviations in the "Symbol" column:

• CC

These parameters indicate **C**ontroller **C**haracteristics, which are distinctive features of the SAL-XC866 and must be regarded for a system design.

SR

These parameters indicate **S**ystem Requirements, which must be provided by the microcontroller system in which the SAL-XC866 is designed in.



4.1.2 Absolute Maximum Rating

Maximum ratings are the extreme limits to which the SAL-XC866 can be subjected to without permanent damage.

| Table 31 | Absolute Maximum Rating Parameters |
|----------|------------------------------------|
|----------|------------------------------------|

| Parameter | Symbol | Limit Values | | Unit | Notes |
|--|-------------------|--------------|--|------|-------------------------------------|
| | | min. | max. | | |
| Ambient temperature | T _A | -40 | 150 | °C | under bias |
| Storage temperature | T _{ST} | -65 | 150 | °C | 1) |
| Junction temperature | TJ | -40 | 160 | °C | under bias ¹⁾ |
| Voltage on power supply pin with respect to $V_{\rm SS}$ | V _{DDP} | -0.5 | 6 | V | 1) |
| Voltage on any pin with respect to $V_{\rm SS}$ | V _{IN} | -0.5 | V _{DDP} + 0.5 or max. 6 | V | Whichever is lower ¹⁾ |
| Input current on any pin during overload condition | I _{IN} | -10 | 10 | mA | 1) |
| Absolute sum of all input currents during overload condition | $\Sigma I_{IN} $ | - | 50 | mA | 1) |

¹⁾ Not subjected to production test, verified by design/characterization.

Note: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. During absolute maximum rating overload conditions ($V_{IN} > V_{DDP}$ or $V_{IN} < V_{SS}$) the voltage on V_{DDP} pin with respect to ground (V_{SS}) must not exceed the values defined by the absolute maximum ratings.



4.1.3 Operating Conditions

The following operating conditions must not be exceeded in order to ensure correct operation of the SAL-XC866. All parameters mentioned in the following table refer to these operating conditions, unless otherwise noted.

Table 32 Operating Condition Parameters

| Parameter | Symbol | Limit | Values | Unit | Notes/ | |
|--------------------------------------|------------------|-------|--------|------|-------------|--|
| | | min. | max. | | Conditions | |
| Digital power supply voltage | V_{DDP} | 4.5 | 5.5 | V | 5V Device | |
| Digital power supply voltage | V _{DDP} | 3.0 | 3.6 | V | 3.3V Device | |
| Digital ground voltage | V _{SS} | (|) | V | | |
| Digital core supply voltage | V _{DDC} | 2.3 | 2.7 | V | | |
| System Clock Frequency ¹⁾ | f _{SYS} | 69 | 81 | MHz | | |
| Ambient temperature | T _A | -40 | 150 | °C | SAL-XC866 | |

¹⁾ f_{SYS} is the PLL output clock. During normal operating mode, CPU clock is f_{SYS} / 3. Please refer to Figure 24 for detailed description.



4.2 DC Parameters

4.2.1 Input/Output Characteristics

Table 33 Input/Output Characteristics (Operating Conditions apply)

| Parameter | Symb | loc | Limit | Values | Unit | Test Conditions |
|--|-------------------|-----|------------------------------|-----------------------------|------|--------------------------|
| | | | min. | max. | | |
| V_{DDP} = 5V Range | 1 | | 1 | I | | |
| Output low voltage | V_{OL} | CC | - | 1.0 | V | I _{OL} = 15 mA |
| | | | - | 0.4 | V | I _{OL} = 5 mA |
| Output high voltage | V _{OH} | CC | V _{DDP} - 1.0 | - | V | I _{OH} = -15 mA |
| | | | V _{DDP} - 0.4 | - | V | I _{OH} = -5 mA |
| Input low voltage on port pins (all except P0.0 & P0.1) | V_{ILP} | SR | - | $0.3 	imes V_{	extsf{DDP}}$ | V | CMOS Mode |
| Input low voltage on P0.0 & P0.1 | V _{ILP0} | SR | -0.2 | $0.3 \times V_{\text{DDP}}$ | V | CMOS Mode |
| Input low voltage on RESET pin | V_{ILR} | SR | - | $0.3 \times V_{\text{DDP}}$ | V | CMOS Mode |
| Input low voltage on TMS pin | V_{ILT} | SR | - | $0.3 \times V_{\text{DDP}}$ | V | CMOS Mode |
| Input high voltage on port pins (all except P0.0 & P0.1) | V _{IHP} | SR | $0.7 	imes V_{ m DDP}$ | - | V | CMOS Mode |
| Input high voltage on P0.0 & P0.1 | V _{IHP0} | SR | $0.7 \times V_{ m DDP}$ | V _{DDP} | V | CMOS Mode |
| Input high voltage on RESET pin | V_{IHR} | SR | $0.7 \times V_{\text{DDP}}$ | - | V | CMOS Mode |
| Input high voltage on TMS pin | V_{IHT} | SR | $0.75 	imes V_{ m DDP}$ | - | V | CMOS Mode |
| Input Hysteresis ¹⁾ on Port Pins | HYS | CC | $0.08 	imes V_{	extsf{DDP}}$ | - | V | CMOS Mode |
| Input Hysteresis ¹⁾ on XTAL1 | HYSX | CC | $0.07 	imes V_{ m DDC}$ | - | V | |



Table 33 Input/Output Characteristics (Operating Conditions apply)

| Parameter | Symbol | | Limit | Values | Unit | Test Conditions | |
|---|-------------------|----|--------------------------|---------------------------|------|---|--|
| | | | min. | max. | | | |
| Input low voltage at XTAL1 | V_{ILX} | SR | V _{SS} - 0.5 | $0.3 	imes V_{ m DDC}$ | V | | |
| Input high voltage at XTAL1 | V_{IHX} | SR | $0.7 \times V_{ m DDC}$ | V _{DDC} + 0.5 | V | | |
| Pull-up current | I _{PU} | SR | - | -10 | μA | V _{IH,min} | |
| | | | -150 | - | μA | V _{IL,max} | |
| Pull-down current | I_{PD} | SR | - | 10 | μA | V _{IL,max} | |
| | | | 150 | - | μA | V _{IH,min} | |
| Input leakage current ²⁾ | I _{OZ1} | CC | -2 | 2 | μA | $0 < V_{IN} < V_{DDP},$ $T_A \le 150^{\circ}C$ | |
| Input current at XTAL1 | I _{ILX} | CC | -10 | 10 | μA | | |
| Overload current on any pin | I _{OV} | SR | -5 | 5 | mA | 3) | |
| Absolute sum of overload currents | $\Sigma I_{OV} $ | SR | - | 25 | mA | 3) | |
| Voltage on any pin during V_{DDP} power off | V _{PO} | SR | - | 0.3 | V | 4) | |
| Maximum current per pin (excluding V_{DDP} and V_{SS}) | I _M | SR | - | 15 | mA | | |
| Maximum current for all pins (excluding $V_{\rm DDP}$ and $V_{\rm SS}$) | $\Sigma I_{M} $ | SR | - | 60 | mA | | |
| Maximum current into V_{DDP} | I _{MVDE} | SR | _ | 80 | mA | 3) | |
| $\begin{array}{c} \text{Maximum current out of} \\ V_{\text{SS}} \end{array}$ | I _{MVSS} | SR | _ | 80 | mA | 3) | |



Table 33 Input/Output Characteristics (Operating Conditions apply)

| Parameter | Symbol | | Limit | Values | Unit | Test Conditions | |
|--|-------------------|----|--|-----------------------------|------|---------------------------|--|
| | | | min. | max. | - | | |
| V_{DDP} = 3.3V Range | | | | 1 1 | | | |
| Output low voltage | V_{OL} | CC | - | 1.0 | V | I _{OL} = 8 mA | |
| | | | - | 0.4 | V | I _{OL} = 2.5 mA | |
| Output high voltage | V _{OH} | CC | V _{DDP} - 1.0 | - | V | I _{OH} = -8 mA | |
| | | | V _{DDP} - 0.4 | - | V | I _{OH} = -2.5 mA | |
| Input low voltage on port pins (all except P0.0 & P0.1) | V _{ILP} | SR | - | $0.3 	imes V_{ m DDP}$ | V | CMOS Mode | |
| Input low voltage on P0.0 & P0.1 | V _{ILP0} | SR | -0.2 | $0.3 	imes V_{	extsf{DDP}}$ | V | CMOS Mode | |
| Input low voltage on RESET pin | V_{ILR} | SR | - | $0.3 	imes V_{	extsf{DDP}}$ | V | CMOS Mode | |
| Input low voltage on TMS pin | V_{ILT} | SR | - | $0.3 	imes V_{ m DDP}$ | V | CMOS Mode | |
| Input high voltage on port pins (all except P0.0 & P0.1) | V_{IHP} | SR | $0.7 \times V_{ m DDP}$ | - | V | CMOS Mode | |
| Input high voltage on P0.0 & P0.1 | V _{IHP0} | SR | $0.7 	imes V_{ m DDP}$ | V _{DDP} | V | CMOS Mode | |
| Input high voltage on RESET pin | V_{IHR} | SR | $0.7 	imes V_{ m DDP}$ | - | V | CMOS Mode | |
| Input high voltage on TMS pin | V_{IHT} | SR | $0.75 	imes V_{ m DDP}$ | - | V | CMOS Mode | |
| Input Hysteresis ¹⁾ on Port Pins | HYS | СС | $0.03 	imes V_{ m DDP}$ | - | V | CMOS Mode | |
| Input Hysteresis ¹⁾ on XTAL1 | HYSX | CC | $\begin{array}{c} 0.07 \times \\ V_{ m DDC} \end{array}$ | - | V | | |
| Input low voltage at XTAL1 | V_{ILX} | SR | V _{SS} - 0.5 | $0.3 	imes V_{ m DDC}$ | V | | |
| Input high voltage at XTAL1 | V_{IHX} | SR | $0.7 	imes V_{ m DDC}$ | V _{DDC} + 0.5 | V | | |



Table 33 Input/Output Characteristics (Operating Conditions apply)

| Parameter | Symbol | | Limit Values | | Unit | Test Conditions | |
|---|-------------------|----|--------------|------|------|---|--|
| | | | min. | max. | | | |
| Pull-up current | I _{PU} | SR | - | -5 | μA | V _{IH,min} | |
| | | | -50 | - | μA | V _{IL,max} | |
| Pull-down current | I_{PD} | SR | - | 5 | μA | V _{IL,max} | |
| | | | 50 | - | μA | V _{IH,min} | |
| Input leakage current ²⁾ | I _{OZ1} | CC | -2 | 2 | μA | $0 < V_{IN} < V_{DDP},$ $T_A \le 150^{\circ}C$ | |
| Input current at XTAL1 | I_{ILX} | CC | - 10 | 10 | μA | | |
| Overload current on any pin | I _{OV} | SR | -5 | 5 | mA | 3) | |
| Absolute sum of overload currents | $\Sigma I_{OV} $ | SR | - | 25 | mA | 3) | |
| Voltage on any pin during V_{DDP} power off | V _{PO} | SR | - | 0.3 | V | 4) | |
| Maximum current per pin (excluding V_{DDP} and V_{SS}) | I _M | SR | - | 15 | mA | | |
| Maximum current for all pins (excluding $V_{\rm DDP}$ and $V_{\rm SS}$) | $\Sigma I_{M} $ | SR | - | 60 | mA | | |
| Maximum current into V_{DDP} | I _{MVDE} | SR | _ | 80 | mA | | |
| Maximum current out of $V_{\rm SS}$ | I _{MVSS} | SR | - | 80 | mA | | |

¹⁾ Not subjected to production test, verified by design/characterization. Hysteresis is implemented to avoid meta stable states and switching due to internal ground bounce. It cannot be guaranteed that it suppresses switching due to external system noise.

²⁾ An additional error current ($l_{IN,I}$) will flow if an overload current flows through an adjacent pin. TMS pin and RESET pin have internal pull devices and are not included in the input leakage current characteristic.

³⁾ Not subjected to production test, verified by design/characterization.

⁴⁾ Not subjected to production test, verified by design/characterization. However, for applications with strict low power-down current requirements, it is mandatory that no active voltage source is supplied at any GPIO pin when VDDP is powered off.







4.2.2 Supply Threshold Characteristics

Figure 35 Supply Threshold Parameters

Table 34 Supply Threshold Parameters (Operating Conditions apply)

| Parameters | Symbol | Symbol | | Limit Values | | | |
|--|--------------------|--------|------|--------------|------|---|--|
| | | | min. | typ. | max. | | |
| V _{DDC} prewarning voltage ¹⁾ | V _{DDCPW} | СС | 2.2 | 2.3 | 2.4 | V | |
| V_{DDC} brownout voltage in active mode ¹⁾ | V _{DDCBO} | СС | 2.0 | 2.1 | 2.2 | V | |
| RAM data retention voltage | VDDCRDR | СС | 0.9 | 1.0 | 1.1 | V | |
| V_{DDC} brownout voltage in power-down mode ²⁾ | VDDCBOPD | CC | 1.3 | 1.5 | 1.7 | V | |
| V _{DDP} prewarning voltage ³⁾ | V _{DDPPW} | СС | 3.3 | 4.0 | 4.65 | V | |
| Power-on reset voltage ²⁾⁴⁾ | VDDCPOR | СС | 1.3 | 1.5 | 1.7 | V | |

¹⁾ Detection is disabled in power-down mode.

²⁾ Detection is enabled in both active and power-down mode.

³⁾ Detection is enabled for external power supply of 5.0V Detection must be disabled for external power supply of 3.3V.

⁴⁾ The reset of EVR is extended by 300 µs typically after the VDDC reaches the power-on reset voltage.



4.2.3 ADC Characteristics

The values in the table below are given for an analog power supply between 4.5 V to 5.5 V. The ADC can be used with an analog power supply down to 3 V. But in this case, the analog parameters may show a reduced performance. All ground pins (V_{SS}) must be externally connected to one single star point in the system. The voltage difference between the ground pins must not exceed 200mV.

| Parameter | arameter Symbol Limit Values | | | Unit | Test Conditions/ | |
|--------------------------------------|-----------------------------------|-------------------------------|------------------|----------------------------|------------------|--|
| | | min. | typ. | max. | | Remarks |
| Analog reference voltage | V _{AREF} SR | V _{AGND} + 1 | V _{DDP} | V _{DDP} + 0.05 | V | 1) |
| Analog reference ground | V _{AGND} SR | V _{SS} - 0.05 | V _{SS} | V _{AREF} - 1 | V | 1) |
| Analog input voltage range | V _{AIN} SR | V _{AGND} | _ | V _{AREF} | V | |
| ADC clocks | f _{ADC} | - | 20 | 40 | MHz | module clock ¹⁾ |
| | f _{ADCI} | - | - | 10 | MHz | internal analog clock ¹⁾ See Figure 32 |
| Sample time | t _S CC | (2 + INF t _{ADCI} | PCR0.ST | FC) × | μs | 1) |
| Conversion time | t _C CC | See Se | ction 4. | 2.3.1 | μs | 1) |
| Total unadjusted | TUE CC | _ | - | 1 | LSB | 8-bit conversion. ²⁾ |
| error | | _ | - | 2 | LSB | 10-bit conversion. ²⁾ |
| Differential Nonlinearity | <i>EA</i> _{DNL} CC | - | 1 | - | LSB | 10-bit conversion ¹⁾ |
| Integral Nonlinearity | <i>EA</i> _{INL} CC | - | 1 | - | LSB | 10-bit conversion ¹⁾ |
| Offset | <i>EA</i> _{OFF} CC | - | 1 | - | LSB | 10-bit conversion ¹⁾ |
| Gain | <i>EA</i> _{GAIN} CC | - | 1 | - | LSB | 10-bit conversion ¹⁾ |
| Overload current coupling factor for | K _{OVA} CC | - | - | 1.0 x 10 ⁻⁴ | - | $I_{\rm OV} > 0^{1)3)$ |
| analog inputs | | - | - | 1.5 x 10 ⁻³ | - | $I_{\rm OV} < 0^{1)3)}$ |

Table 35 ADC Characteristics (Operating Conditions apply; V_{DDP} = 5V Range)



| Table 35 | ADC Characteristics (Operating Conditions apply; V_{DDP} = 5V Range) |
|----------|---|
|----------|---|

| Parameter | Symbol | Li | mit Value | es | Unit | Test Conditions/ | |
|--|-----------------------------|------|-----------|---------------------------|------|-------------------------|--|
| | | min. | typ. | max. | | Remarks | |
| Overload current coupling factor for | K _{OVD} CC | - | - | 5.0 x 10 ⁻³ | - | $I_{\rm OV} > 0^{1)3)}$ | |
| digital I/O pins | | - | - | 1.0 x 10 ⁻² | - | $I_{\rm OV} < 0^{1)3)}$ | |
| Switched capacitance at the reference voltage input | C _{AREFSW} CC | _ | 10 | 20 | рF | 1)4) | |
| Switched capacitance at the analog voltage inputs | C _{AINSW} CC | _ | 5 | 7 | pF | 1)5) | |
| Input resistance of the reference input | <i>R</i> _{AREF} CC | - | 1 | 2 | kΩ | 1) | |
| Input resistance of the selected analog channel | R _{AIN} CC | - | 1 | 1.5 | kΩ | 1) | |

¹⁾ Not subject to production test, verified by design/characterization.

²⁾ TUE is tested at $V_{AREF} = 5.0 \text{ V}$, $V_{AGND} = 0 \text{ V}$, $V_{DDP} = 5.0 \text{ V}$.

- ³⁾ An overload current (I_{OV}) through a pin injects a certain error current (I_{INJ}) into the adjacent pins. This error current adds to the respective pin's leakage current (I_{OZ}). The amount of error current depends on the overload current and is defined by the overload coupling factor K_{OV} . The polarity of the injected error current is inverse compared to the polarity of the overload current that produces it. The total current through a pin is $|I_{TOT}| = |I_{OZ1}| + (|I_{OV}| \times K_{OV})$. The additional error current may distort the input voltage on analog inputs.
- ⁴⁾ This represents an equivalent switched capacitance. This capacitance is not switched to the reference voltage at once. Instead of this, smaller capacitances are successively switched to the reference voltage.
- ⁵⁾ The sampling capacity of the conversion C-Network is pre-charged to $V_{AREF}/2$ before connecting the input to the C-Network. Because of the parasitic elements, the voltage measured at ANx is lower than $V_{AREF}/2$.







4.2.3.1 ADC Conversion Timing

Conversion time, $t_C = t_{ADC} \times (1 + r \times (3 + n + STC))$, where r = CTC + 2 for $CTC = 00_B$, 01_B or 10_B , r = 32 for $CTC = 11_B$, CTC = Conversion Time Control (GLOBCTR.CTC), STC = Sample Time Control (INPCR0.STC), n = 8 or 10 (for 8-bit and 10-bit conversion respectively), $t_{ADC} = 1 / f_{ADC}$



4.2.4 Power Supply Current

Table 36 Power Supply Current Parameters (Operating Conditions apply)

| Parameter | Symbol | Limit | /alues | Unit | Test Condition |
|------------------------------------|------------------|--------------------|--------------------|------|-----------------------|
| | | typ. ¹⁾ | max. ²⁾ | | |
| Active Mode | I _{DDP} | 22.6 | 25.1 | mA | 3) |
| Idle Mode | I _{DDP} | 17.2 | 19.7 | mA | 4) |
| Active Mode with slow-down enabled | I _{DDP} | 7.2 | 9.3 | mA | 5) |
| Idle Mode with slow-down enabled | I _{DDP} | 7.1 | 8 | mA | 6) |

¹⁾ The typical I_{DDP} values are periodically measured at T_{A} = + 25 °C and V_{DDP} = 5.0 V.

- ²⁾ The maximum I_{DDP} values are measured under worst case conditions (T_{A} = + 150 °C and V_{DDP} = 5.5 V).
- ³⁾ I_{DDP} (active mode) is measured with: CPU clock and input clock to all peripherals running at 25 MHz(set by on-chip oscillator of 10 MHz and NDIV in PLL_CON to 0001_B), RESET = V_{DDP}.
- ⁴⁾ I_{DDP} (idle mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enabled and running at 25 MHz, RESET = V_{DDP}.
- ⁵⁾ I_{DDP} (active mode with slow-down mode) is measured with: CPU clock and input clock to all peripherals running at 781 KHz by setting CLKREL in CMCON to 0101_B, RESET = V_{DDP}.
- ⁶⁾ I_{DDP} (idle mode with slow-down mode) is measured with: CPU clock disabled, watchdog timer disabled, input <u>clock to</u> all peripherals enabled and running at 781 MHz by setting CLKREL in CMCON to 0101_B, <u>RESET</u> = V_{DDP}.



Table 37 Power Down Current (Operating Conditions apply)

| Parameter | Symbol | Limit Values | | Limit Values | | Unit | Test Condition |
|-------------------------------|------------------|--------------------|--------------------|--------------|--|------|-----------------------|
| | | typ. ¹⁾ | max. ²⁾ | | | | |
| Power-Down Mode ³⁾ | I _{PDP} | 1 | 10 | μA | $T_{\rm A} = + 25 \ {}^{\circ}{\rm C.}^{4)}$ | | |
| | | - | 30 | μA | $T_{A} = +85 \text{ °C.}^{4)5)}$ | | |

¹⁾ The typical I_{PDP} values are measured at $V_{DDP} = 5.0$ V.

²⁾ The maximum I_{PDP} values are measured at V_{DDP} = 5.5 V.

³⁾ I_{PDP} (power-down mode) has a maximum value of 500 µA at T_A = + 150 °C.

⁴⁾ I_{PDP} (power-down mode) is measured with: RESET = V_{DDP}, V_{AGND}= V_{SS}, RXD/INT0 = V_{DDP}; rest of the ports are programmed to be input with either internal pull devices enabled or driven externally to ensure no floating inputs.

⁵⁾ Not subject to production test, verified by design/characterization.



4.3 AC Parameters

4.3.1 Testing Waveforms

The testing waveforms for rise/fall time, output delay and output high impedance are shown in Figure 37, Figure 38 and Figure 39.



Figure 37 Rise/Fall Time Parameters



Figure 38 Testing Waveform, Output Delay



Figure 39 Testing Waveform, Output High Impedance



4.3.2 Output Rise/Fall Times

Table 38 Output Rise/Fall Times Parameters (Operating Conditions apply)

| Parameter | Symbol | Limit Values | | Unit | Test Conditions |
|-------------------------------|---------------------------------|-----------------|-----------|------|----------------------|
| | | min. | min. max. | | |
| V_{DDP} = 5V Range | | | | | |
| Rise/fall times 1) 2) | t _R , t _F | - | 10 | ns | 20 pF. ³⁾ |
| V_{DDP} = 3.3V Range | | | I. | | |
| Rise/fall times 1) 2) | t _R , t _F | - | 10 | ns | 20 pF. ⁴⁾ |

¹⁾ Rise/Fall time measurements are taken with 10% - 90% of the pad supply.

²⁾ Not all parameters are 100% tested, but are verified by design/characterization and test correlation.

³⁾ Additional rise/fall time valid for $C_L = 20pF - 100pF$ @ 0.125 ns/pF.

 $^{\rm 4)}\,$ Additional rise/fall time valid for CL = 20pF - 100pF @ 0.225 ns/pF.



Figure 40 Rise/Fall Times Parameters



4.3.3 Power-on Reset and PLL Timing

Table 39 Power-On Reset and PLL Timing (Operating Conditions apply)

| Parameter | Symbol | Limit Values | | | Unit | Test Conditions | | |
|-------------------------------------|--------------------------|--------------|------|------|------|--|--|--|
| | | min. | typ. | max. | | | | |
| Pad operating voltage | V _{PAD} CC | 2.3 | - | - | V | 1) | | |
| On-Chip Oscillator start-up time | t _{OSCST} CC | _ | - | 500 | ns | 1) | | |
| Flash initialization time | t _{FINIT} CC | _ | 160 | _ | μs | 1) | | |
| RESET hold time | t _{RST} SR | _ | 500 | - | μs | V_{DDP} rise time (10% - 90%) \leq 500µs ¹⁾²⁾ | | |
| PLL lock-in in time | t _{LOCK} CC | _ | - | 200 | μs | 1) | | |
| PLL accumulated jitter | D _P | - | - | 0.7 | ns | 1) | | |

¹⁾ Not all parameters are 100% tested, but are verified by design/characterization and test correlation.

²⁾ RESET signal has to be active (low) until V_{DDC} has reached 90% of its maximum value (typ. 2.5V).



Figure 41 Power-on Reset Timing



4.3.4 On-Chip Oscillator Characteristics

| Table 40 | On-chip Oscillator | Characteristics | (Operating | Conditions apply |) |
|----------|--------------------|-----------------|------------|-------------------------|---|
|----------|--------------------|-----------------|------------|-------------------------|---|

| Parameter | Symbol | Lir | Limit Values | | | Test Conditions | | |
|--------------------------------|---------------------|------|--------------|-------|-----|--|--|--|
| | | min. | typ. | max. | | | | |
| Nominal frequency | f _{NOM} CC | 9.75 | 10 | 10.25 | MHz | under nominal conditions ¹⁾ | | |
| Long term frequency deviation | Δf_{LT} CC | 0 | - | 6.0 | % | with respect to f_{NOM} , over lifetime and temperature (125°C to 150°C), for one device after trimming | | |
| | | -5.0 | - | 5.0 | % | with respect to f_{NOM} , over lifetime and temperature $(-10^{\circ}C \text{ to } 125^{\circ}C)$, for one device after trimming | | |
| | | -6.0 | - | 0 | % | with respect to f_{NOM} , over lifetime and temperature (-40°C to -10°C), for one device after trimming | | |
| Short term frequency deviation | Δf_{ST} CC | -1.0 | - | 1.0 | % | within one LIN message (<10 ms 100 ms) | | |

¹⁾ Nominal condition: $V_{DDC} = 2.5 \text{ V}, T_A = +25^{\circ}\text{C}.$



4.3.5 JTAG Timing

Table 41 TCK Clock Timing (Operating Conditions apply; $C_{L} = 50 \text{ pF}$)

| Parameter | Symbol | Limits | | Unit |
|-----------------------------------|---------------------|--------|-----|------|
| | | min | max | |
| TCK clock period ¹⁾ | t _{TCK} SR | 50 | - | ns |
| TCK high time ¹⁾ | t ₁ SR | 20 | - | ns |
| TCK low time ¹⁾ | t ₂ SR | 20 | - | ns |
| TCK clock rise time ¹⁾ | t ₃ SR | _ | 4 | ns |
| TCK clock fall time ¹⁾ | t ₄ SR | - | 4 | ns |

¹⁾ Not all parameters are 100% tested, but are verified by design/characterization and test correlation.



Figure 42 TCK Clock Timing



| <i>C</i> _L = 50 pF) | |
|--------------------------------|-------------------------|
| | C _L = 50 pF) |

| Parameter | | nbol | Limits | | Unit |
|--|-----------------------|------|--------|-----|------|
| | | | min | max | |
| TMS setup to TCK ¹⁾ | <i>t</i> ₁ | SR | 8.0 | - | ns |
| TMS hold to TCK ¹⁾ | <i>t</i> ₂ | SR | 5.0 | - | ns |
| TDI setup to TCK ¹⁾ _ | <i>t</i> ₁ | SR | 11.0 | - | ns |
| TDI hold to TCK ¹⁾ | <i>t</i> ₂ | SR | 6.0 | - | ns |
| TDO valid output from TCK ¹⁾ – | t_3 | CC | - | 23 | ns |
| TDO high impedance to valid output from TCK ¹⁾ \neg | <i>t</i> ₄ | CC | - | 26 | ns |
| TDO valid output to high impedance from TCK ¹⁾ \neg | t_5 | CC | - | 18 | ns |

¹⁾ Not all parameters are 100% tested, but are verified by design/characterization and test correlation.






Electrical Parameters

4.3.6 SSC Master Mode Timing

Table 43 SSC Master Mode Timing (Operating Conditions apply; CL = 50 pF)

| Parameter | | mbol | Limit | Unit | |
|-------------------------------------|-----------------------|------|-----------------------|------|----|
| | | | min. | max. | |
| SCLK clock period ¹⁾ | t ₀ | CC | 2*T _{SSC} 2) | - | ns |
| MTSR delay from SCLK ¹⁾ | <i>t</i> ₁ | CC | 0 | 8 | ns |
| MRST setup to SCLK ¹⁾ | <i>t</i> ₂ | SR | 22 | _ | ns |
| MRST hold from SCLK ¹⁾ - | t_3 | SR | 0 | - | ns |

¹⁾ Not all parameters are 100% tested, but are verified by design/characterization and test correlation.

²⁾ $T_{SSCmin} = T_{CPU} = 1/f_{CPU}$. When $f_{CPU} = 25$ MHz, $t_0 = 80$ ns. T_{CPU} is the CPU clock period.



Figure 44 SSC Master Mode Timing



Package and Reliability

5 Package and Reliability

5.1 Package Parameters (PG-TSSOP-38)

Table 44 provides the thermal characteristics of the package.

| Table 44 | Thermal | Characteristics | of | the | Package |
|----------|---------|------------------------|----|-----|---------|
|----------|---------|------------------------|----|-----|---------|

| Parameter | Symbol | | Limit | t Values | Unit | Notes |
|--|------------------|----|-------|----------|------|-------|
| | | | Min. | Max. | | |
| Thermal resistance junction case ¹⁾²⁾ | R _{TJC} | СС | - | 15.7 | K/W | - |
| Thermal resistance junction lead ¹⁾²⁾ | R _{TJL} | СС | - | 39.2 | K/W | - |

⁾ The thermal resistances between the case and the ambient (R_{TCA}), the lead and the ambient (R_{TLA}) are to be combined with the thermal resistances between the junction and the case (R_{TJC}), the junction and the lead (R_{TJL}) given above, in order to calculate the total thermal resistance between the junction and the ambient (R_{TJA}). The thermal resistances between the case and the ambient (R_{TCA}), the lead and the ambient (R_{TLA}) depend on the external system (PCB, case) characteristics, and are under user responsibility.

The junction temperature can be calculated using the following equation: $T_J=T_A + R_{TJA} \times P_D$, where the R_{TJA} is the total thermal resistance between the junction and the ambient. This total junction ambient resistance R_{TJA} can be obtained from the upper four partial thermal resistances, by

a) simply adding only the two thermal resistances (junction lead and lead ambient), or

b) by taking all four resistances into account, depending on the precision needed.

²⁾ Not all parameters are 100% tested, but are verified by design/characterization and test correlation.



Package and Reliability

5.2 Package Outline



Figure 45 PG-TSSOP-38-4 Package Outline



Package and Reliability

5.3 Quality Declaration

Table 45 shows the characteristics of the quality parameters in the SAL-XC866.

Table 45Quality Parameters

| Parameter | Symbol | Limit Values | | | Unit | Notes | |
|--|-------------------|--------------|------|--------|-------|--|--|
| | | Min. | Тур. | Max. | | | |
| Operation Lifetime when the device is used at the four stated $T_A^{(1)2)}$ | t _{OP} | - | - | 500 | hours | <i>T</i> _A = 150°C | |
| | | - | - | 1000 | hours | <i>T</i> _A = 140°C | |
| | | - | - | 2000 | hours | <i>T</i> _A = 125°C | |
| | | - | - | 10000 | hours | <i>T</i> _A = 85°C | |
| | | - | - | 1500 | hours | $T_{\rm A}$ = -40°C | |
| Operation Lifetime when the device is used at the two stated $T_A^{1/2}$ | t _{OP2} | _ | - | 18000 | hours | <i>T</i> _A = 108°C | |
| | | - | - | 130000 | hours | <i>T</i> _A = 27°C | |
| Weighted Average Temperature ²⁾³⁾ | T_{WA} | _ | 107 | _ | °C | for 15000 hours | |
| ESD susceptibility according to Human Body Model (HBM) for all pins (except V_{DDC}) ²⁾ | V _{HBM} | - | - | 2000 | V | Conforming to EIA/JESD22- A114-B | |
| ESD susceptibility according to Human Body Model (HBM) for V _{DDC} ²⁾ | V _{HBMC} | - | - | 600 | V | Conforming to EIA/JESD22- A114-B | |
| ESD susceptibility according to Charged Device Model (CDM) pins ²⁾ | V _{CDM} | - | - | 750 | V | Conforming to JESD22-C101-C | |

¹⁾ This lifetime refers only to the time when the device is powered-on.

²⁾ Not all parameters are 100% tested, but are verified by design/characterization and test correlation.

³⁾ This parameter is derived based on the Arrhenius model.

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